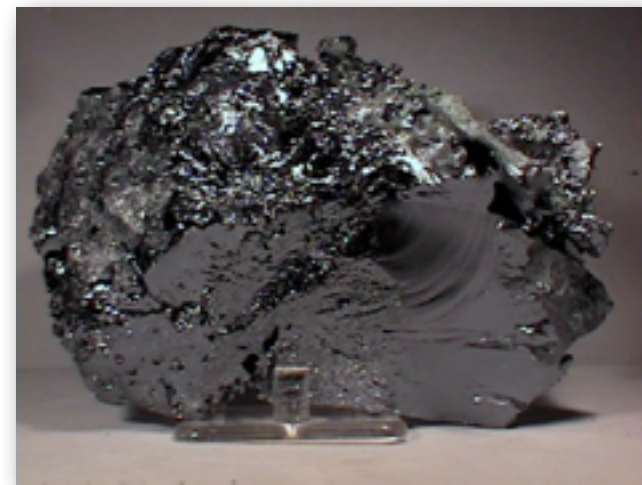


MATERIAL PROPERTIES

	Si	Ge	GaAs	CdTe	Diamond	SiC
band gap	1.12	0.67	1.42	1.56	5.48	2.99
energy for e-p pair [eV]	3.6	2.9	4.2	4.7	13.1	6.9
e- for MIP (300 μ m)	24000	50000	35000	35000	9300	19000
Z	14	32	31+33	48+52	6	14+6

Why is silicon used more often ?

- Silicon is the only material which can be produced in larger areas in high quality
- compare to $kT = 0.026$ eV at room temperature -> dark current under control
- high density compared to gases: $\rho = 2.33 \text{g/cm}^3$
- good mechanical stability -> possible to produce mechanically stable layers
- large charge carrier mobility
- fast charge collection $\delta t \sim 10 \text{ns}$
- well understood -> radiation tolerant



PRINCIPLE OF SEMICONDUCTOR

- Creation of electric field: voltage to deplete thickness d

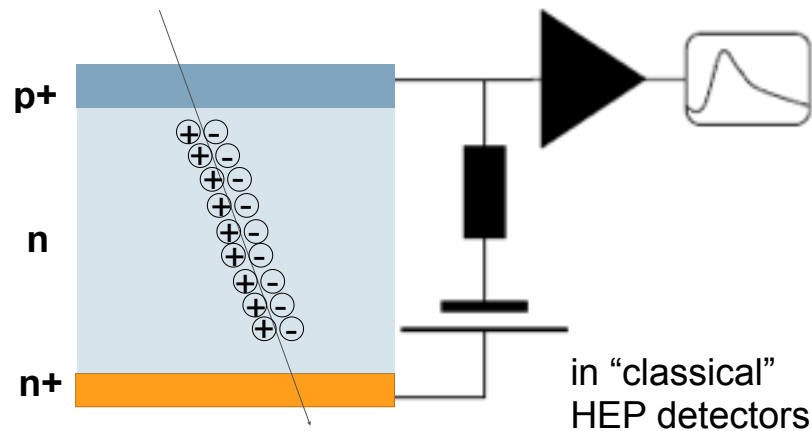
with $n_A \gg n_D$

$$d = \sqrt{\frac{2\epsilon\epsilon_0 V_{dep}}{en_D}}$$

for $d = 300\mu m$ $V_{dep} \approx 160V$

- Passage of a charged particle: Electron-hole pairs formed in the depletion zone
 - Drift under the influence of the electric field
 - Signal depends on width of depletion zone

The signal is induced by the motion of charge after incident radiation (not when the charge reaches the electrodes).



Typical numbers

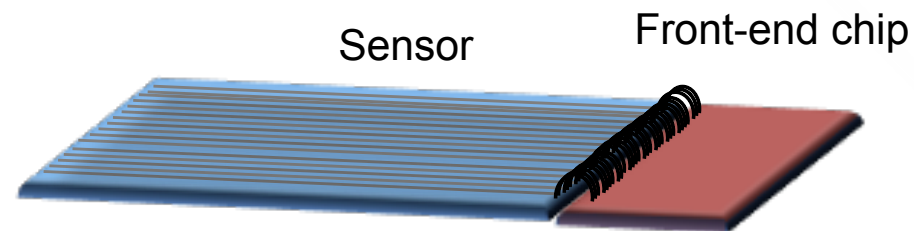
Doping concentration

$n_A \approx 10^{19} cm^{-3}$ Acceptors

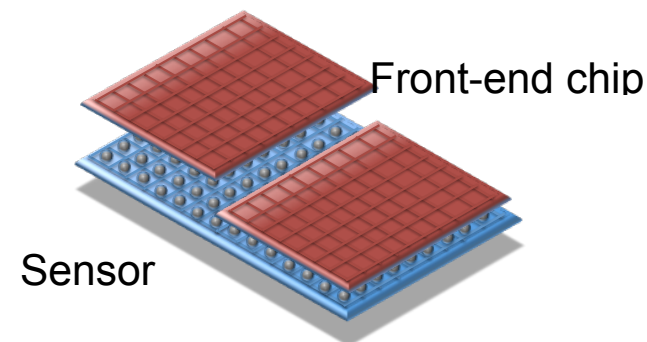
$n_D \approx 2 \cdot 10^{12} cm^{-3}$ Donators

STRIPS AND PIXELS

- **Strips detector:** charge sensed by long narrow strips 1D information (typically 20 - 100 μ m)
 - 2D information by double sided processing or adding back to back second layer slightly rotated (stereo angle)
- In regions with higher track density one dimensional measurements can lead to ambiguities.
- **Pixel detector:** charge sensed by small pixels on one side of sensor
 - Hybrid pixels: sensors and readout joined via bump bonds
 - Monolithic pixels: sensor and readout on one substrate



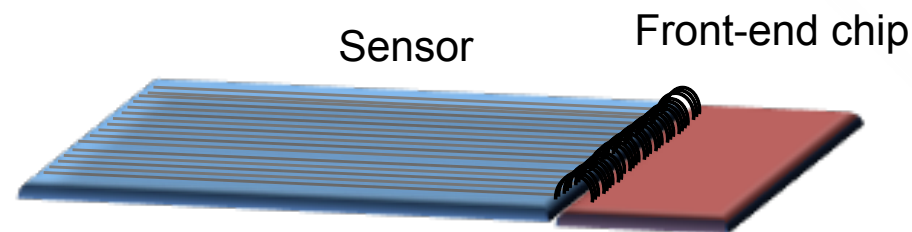
Microstrips detector



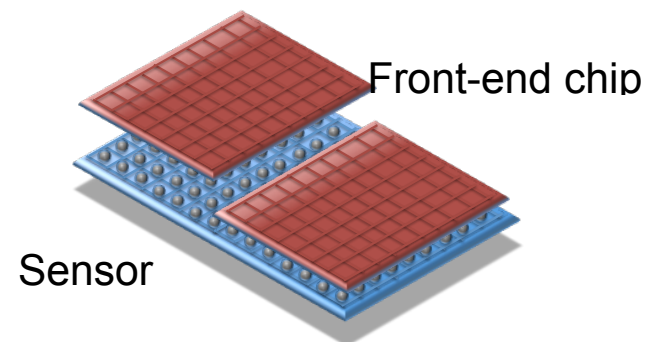
Hybrid pixel detector

STRIPS AND PIXELS

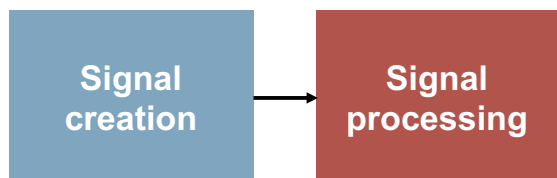
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Microstrips detector

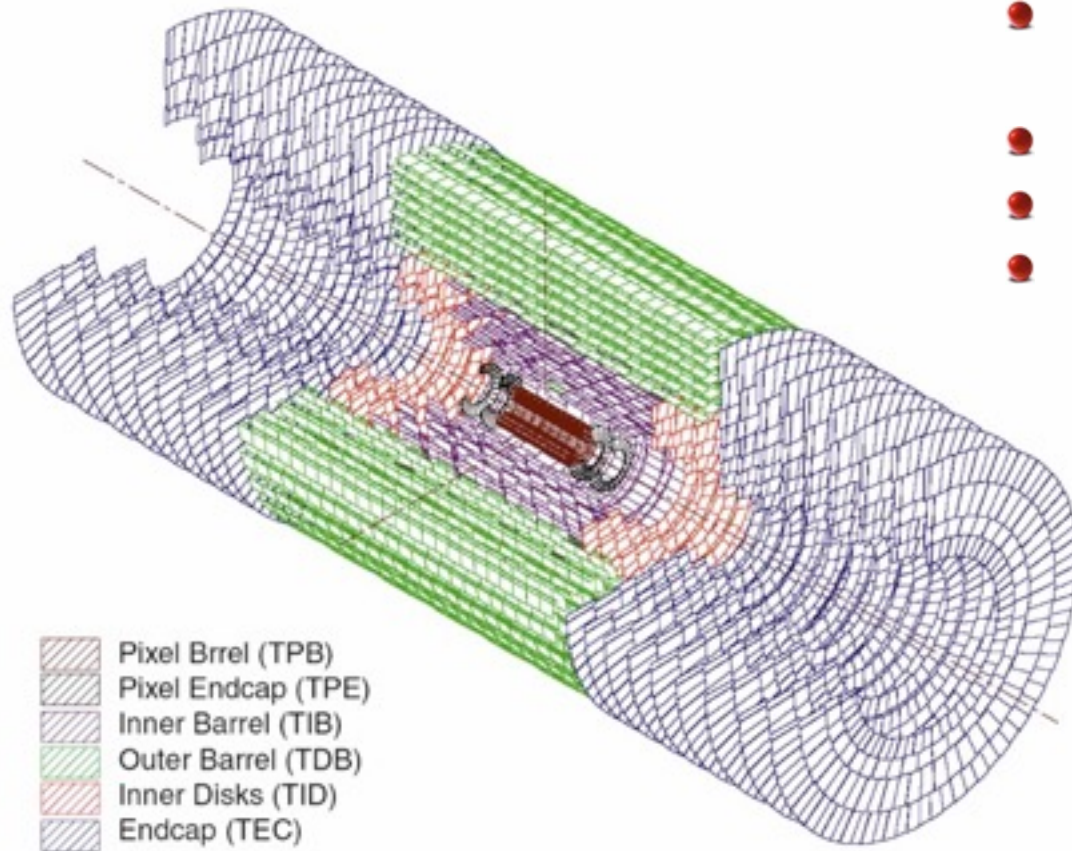


Hybrid pixel detector

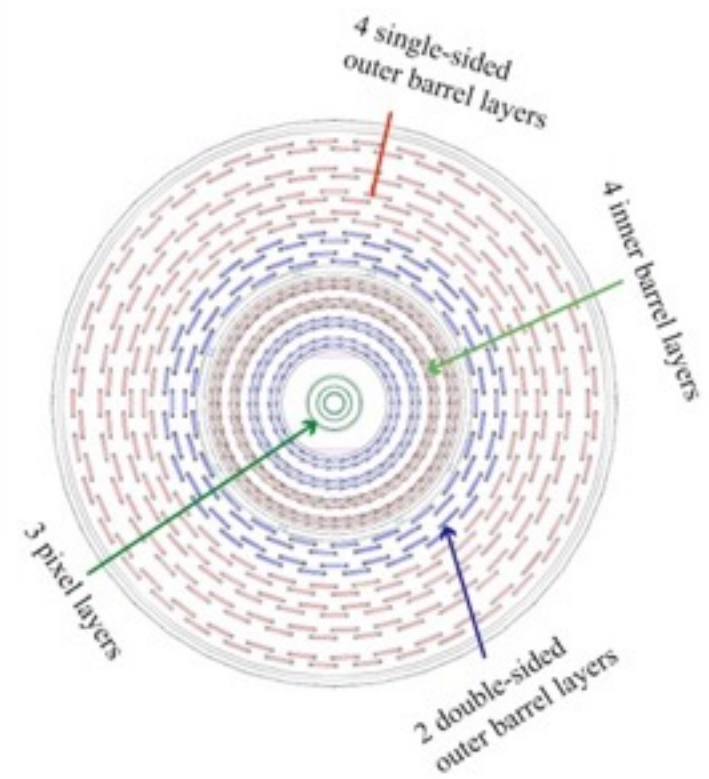


- Signals created in silicon by charged particle
 - Very small signals (fC): need amplification
 - Measurement of amplitude/hit and/or time
 - Several thousands to millions of channels

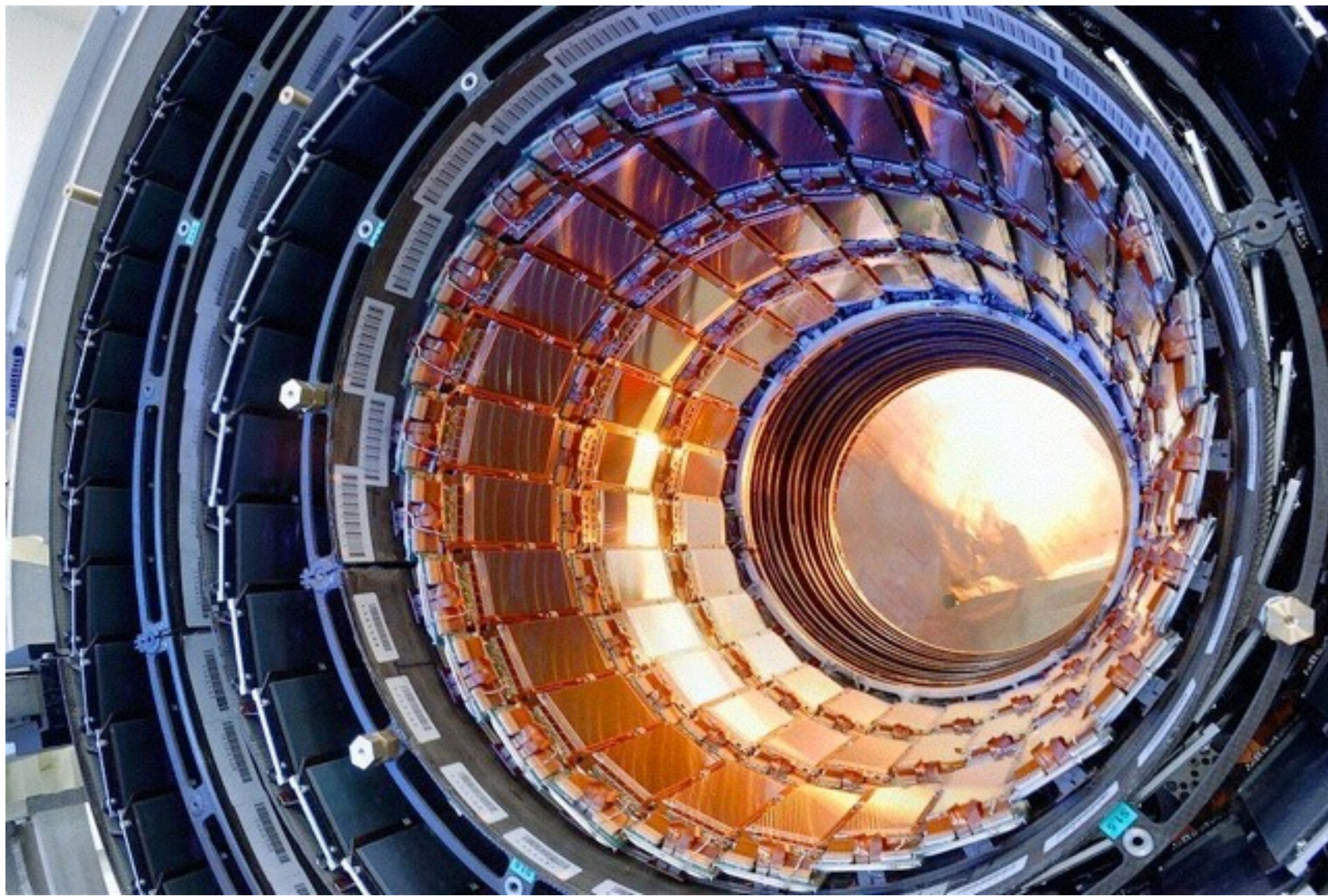
CMS SI-TRACKER



- Si-Strip-Detector:
- ~ 205 m² Silicon
- 25 000 Sensors, 9.6 M channels
- 10 barrel layers, 2x 9 discs
- The largest ever built silicon tracker

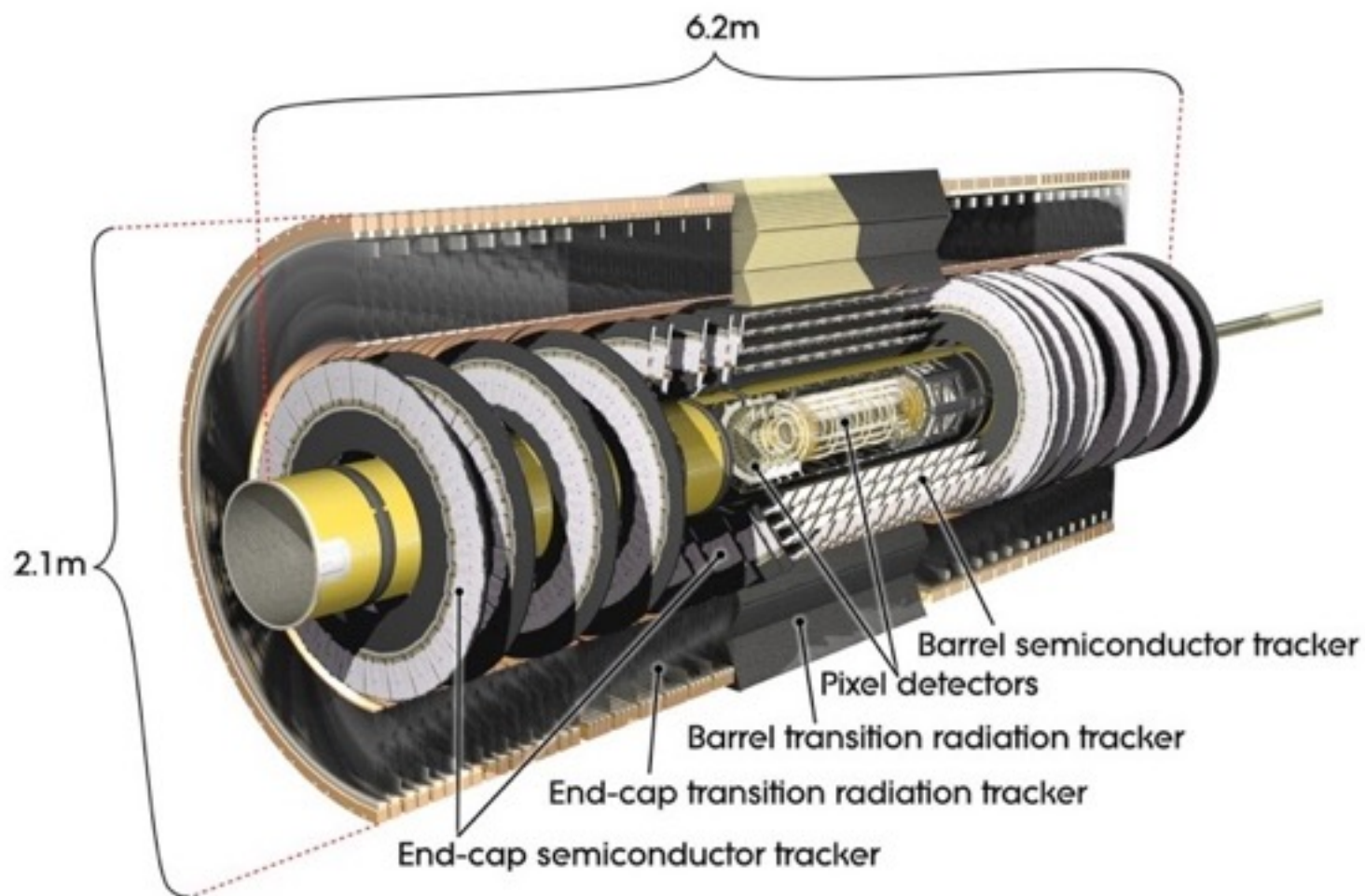


CMS TRACKER - BEAUTY SHOT



Pic: CERN

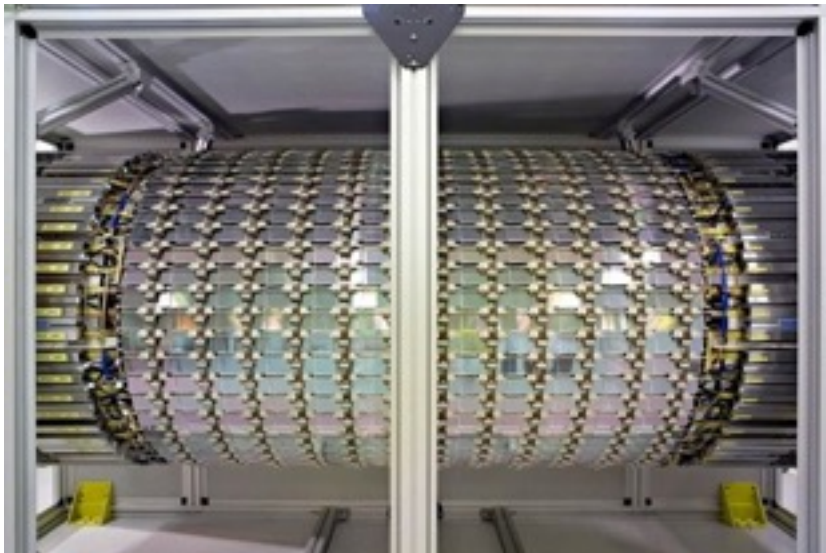
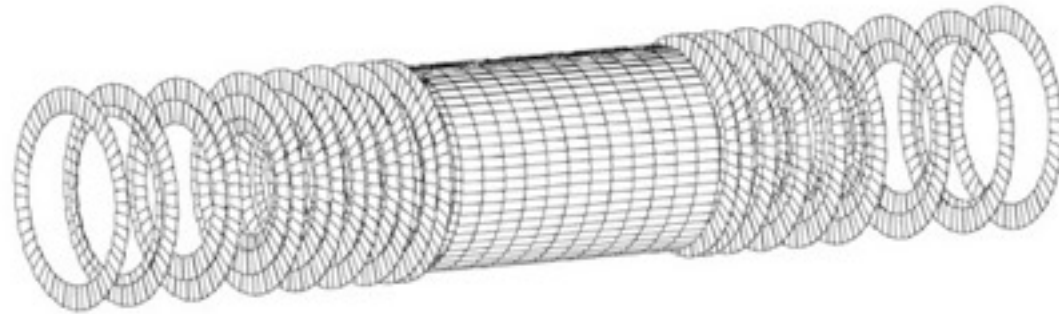
ATLAS SCT



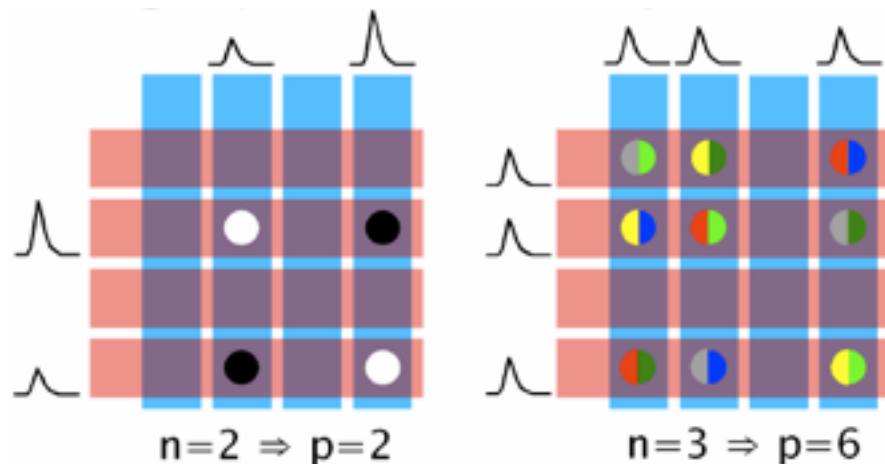
- ATLAS Si-Detector SCT:
- Si- strips: 4 Barrel-layer, 2 x 9 discs

ATLAS SCT

- SCT strips:
 - 61 m² silicon, ~6.2 M channels
 - 4088 modules, 2112 barrel (1 type), 1976 in the discs (4 different types)



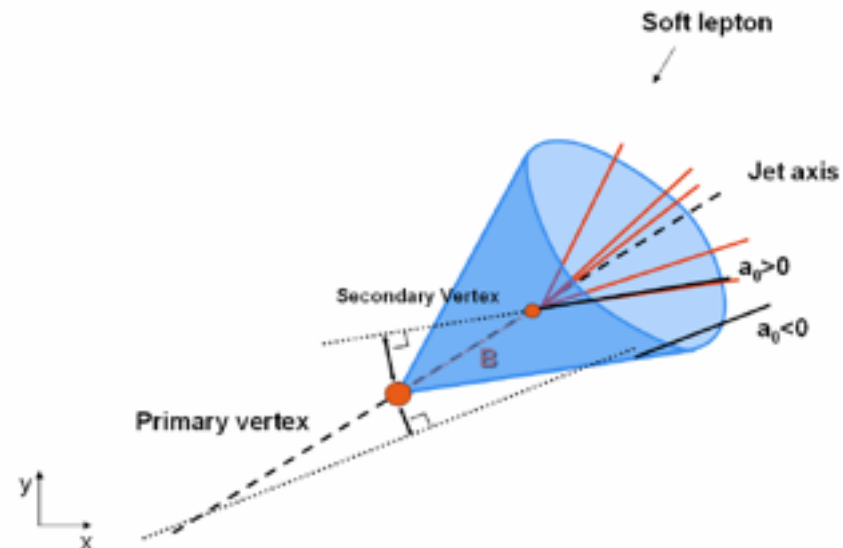
LIMITS OF STRIP DETECTORS



● In case of high hit density ambiguities give difficulties for the track reconstruction

● Deriving the point resolution from just one coordinate is not enough information to reconstruct a secondary vertex

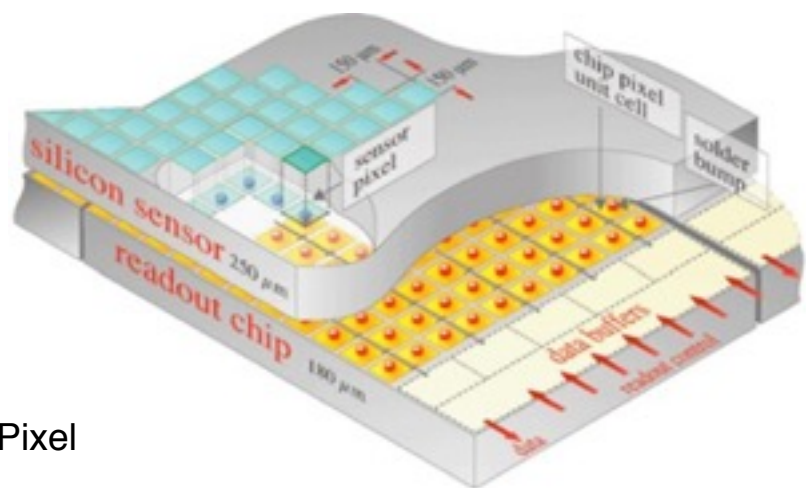
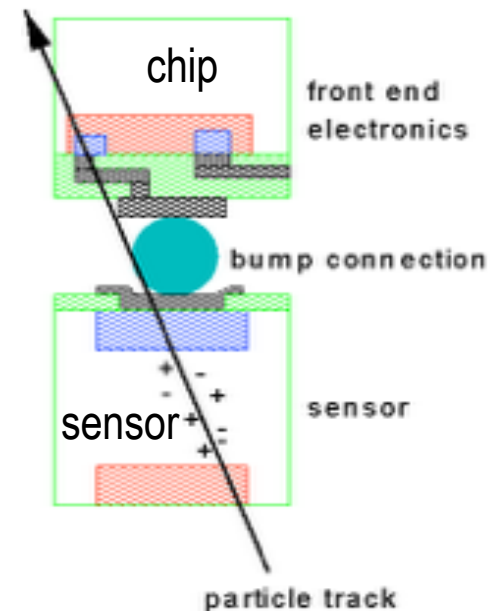
- Pixel detectors allow track reconstruction at high particle rate without ambiguities
- Good resolution with two coordinates (depending on pixel size and charge sharing between pixels)
- Very high channel number: complex read-out
- Readout in active area a detector



**First pixels (CCDs)
in NA11/NA32: ~1983**

HYBRID PIXELS – “CLASSICAL” CHOICE HEP

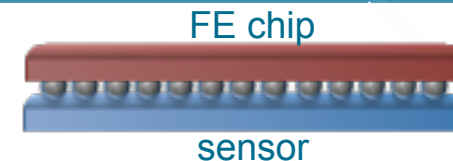
- The read-out chip is mounted directly on top of the pixels (bump-bonding)
 - Each pixel has its own read-out amplifier
 - Can choose proper process for sensor and read-out separately
 - Fast read-out and radiation-tolerant
- ... but:
- Pixel area defined by the size of the read-out chip
 - High material budget and high power dissipation



- CMS Pixels: ~65 M channels
150 μm x 150 μm
- ATLAS Pixels: ~80 M channels
50 μm x 400 μm (long in z or r)
- Alice: 50 μm x 425 μm
- LHCb
- Phenix@RHIC
-

Hybrid Pixel
(CMS)

SENSORS FOR HYBRID PIXELS



Planar Sensor

- current design is an n-in-n planar sensor
- silicon diode
- different designs under study (n-in-n; n-in-p)
- radiation hardness proven up to $2.4 \cdot 10^{16}$ p/cm²
- problem: HV might need to exceed 1000V

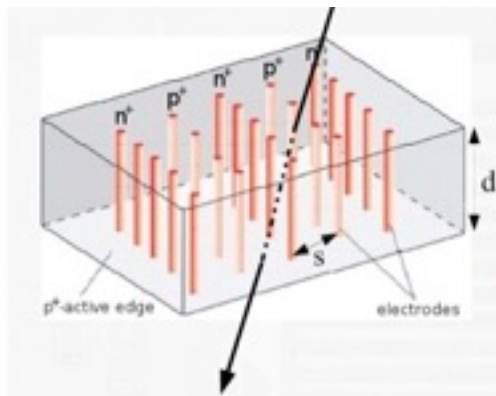
3D Silicon

- Both electrode types are processed inside the detector bulk instead of being implanted on the wafer's surface.
- Max. drift and depletion distance set by electrode spacing
- Reduced collection time and depletion voltage
- Low charge sharing

CVD (Diamond)

- Poly crystalline and single crystal
- Low leakage current, low noise, low capacitance
- Radiation hard material
- Operation at room temperature possible
- Drawback: 50% signal compared to silicon for same X_0 , but better S/N ratio (no dark current)

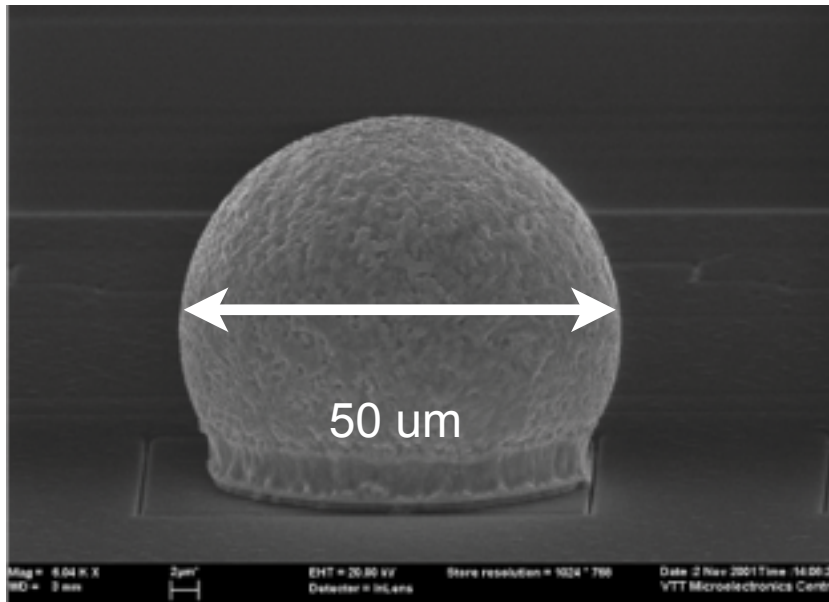
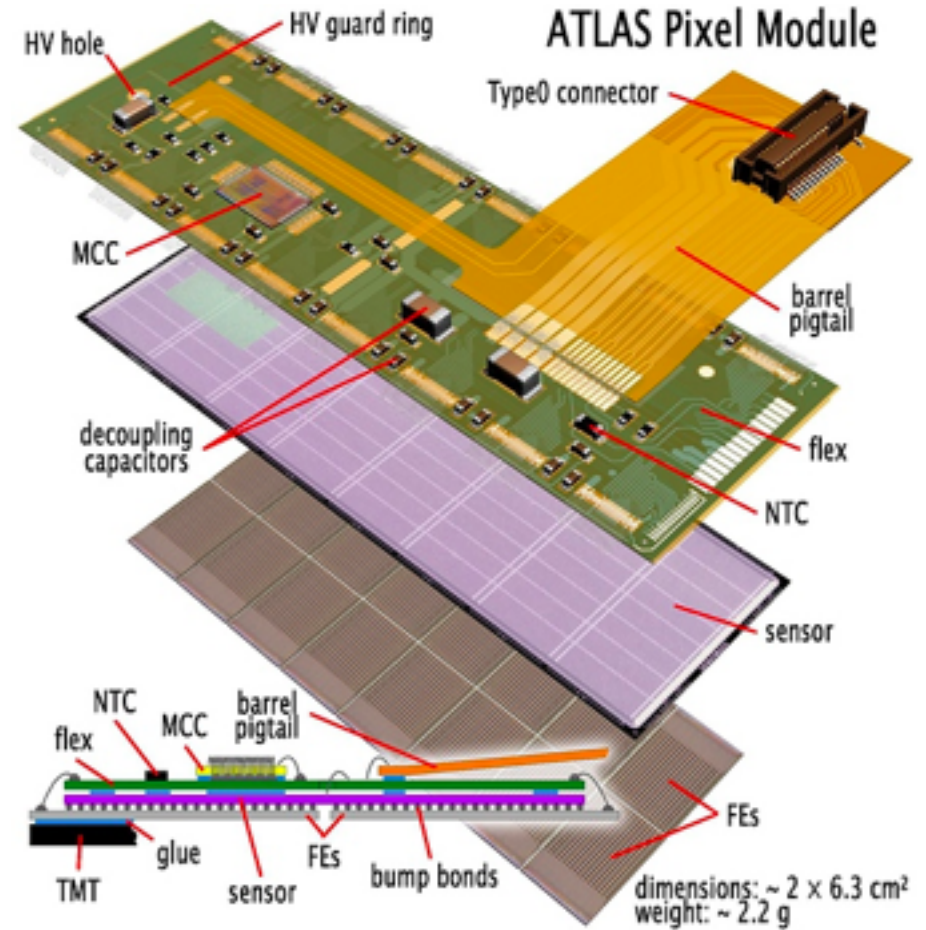
Very strong R&D efforts to develop sensors for future LHC applications!



ATLAS-PIXELS

A pixel module contains:

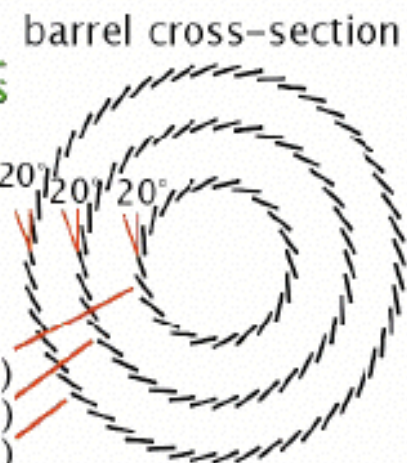
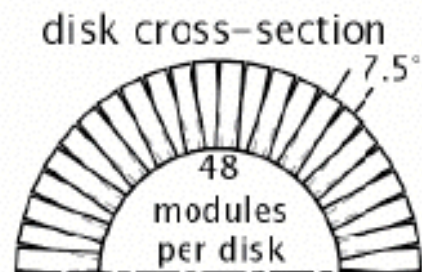
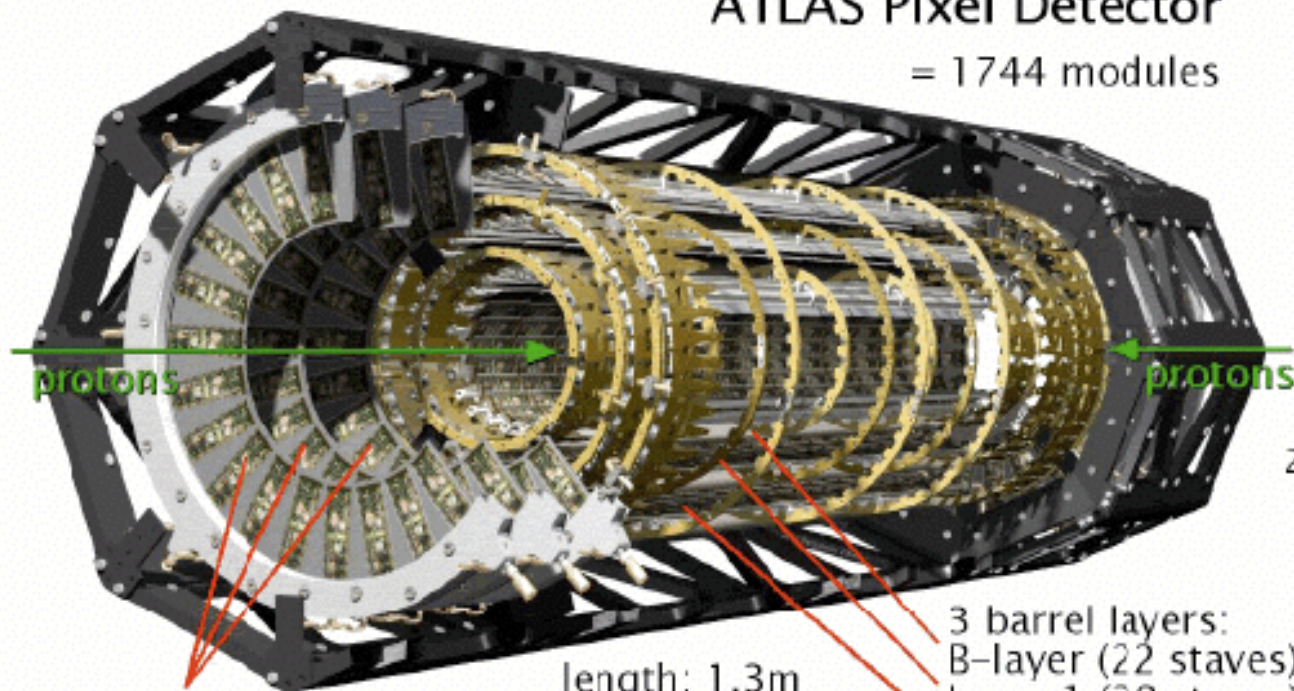
- 1 sensor (2x6cm)
- ~40000 pixels (50x500 nm)
- 16 front end (FE) chips
- 2x8 array
- bump bonded to sensor
- Flex-hybrid
- 1 module control chip (MCC)
- There are ~1700 modules



Picture: VTT

ATLAS-PIXELS

ATLAS Pixel Detector
= 1744 modules

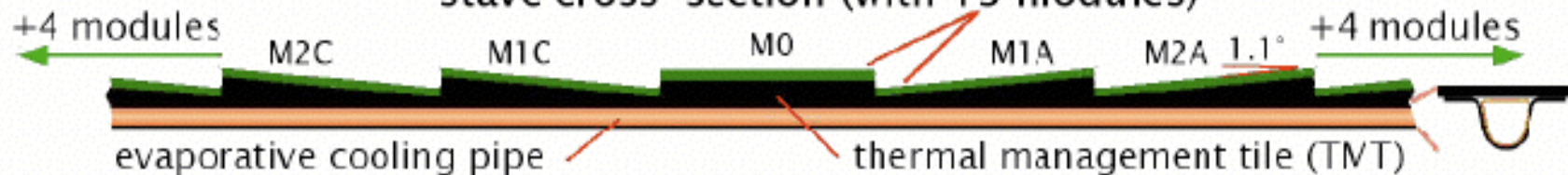


3 barrel layers:
B-layer (22 staves)
Layer 1 (38 staves)
Layer 2 (52 staves)

3 disks, each with 8 sectors and 48 modules

length: 1.3m
Ø: 34.4 cm
weight: ~ 4.4 kg

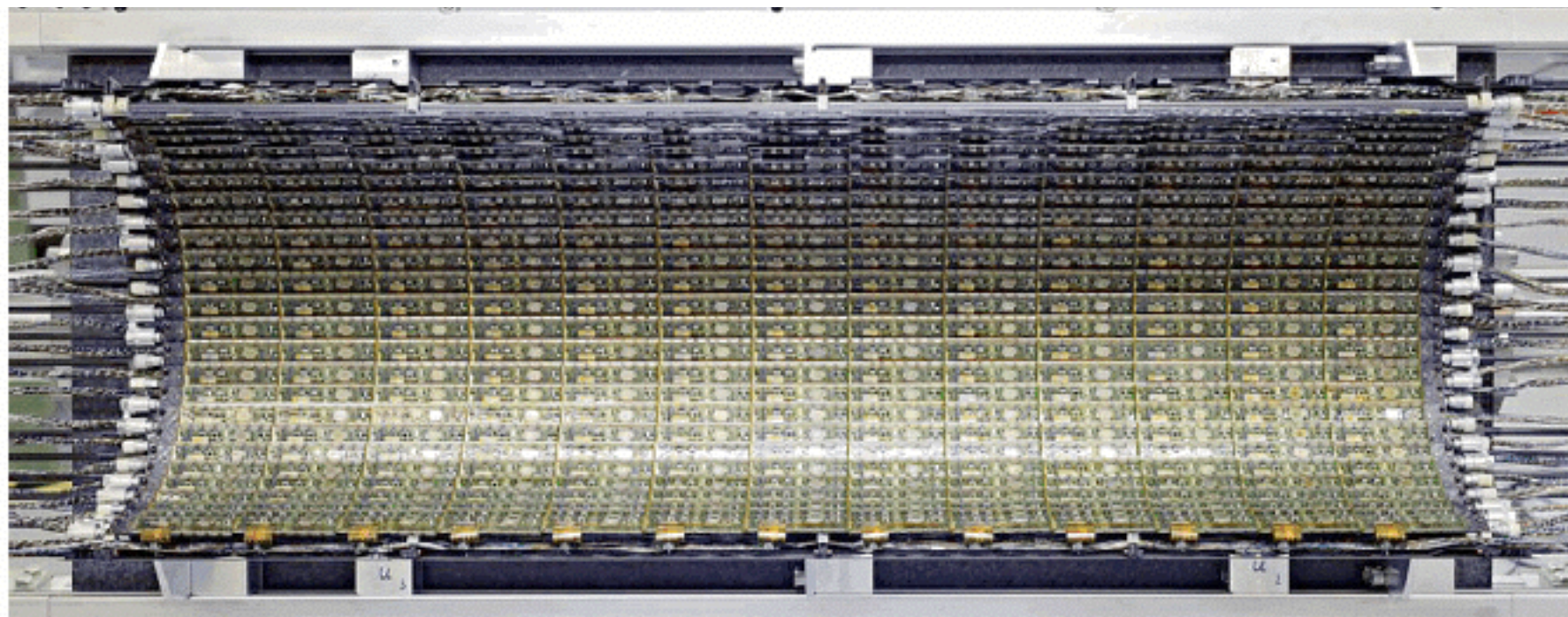
stave cross-section (with 13 modules)





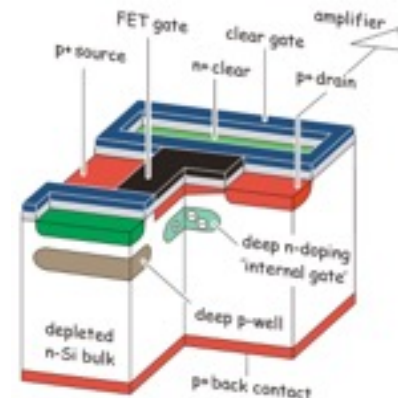
ATLAS-PIXELS

ATLAS-PIXELS

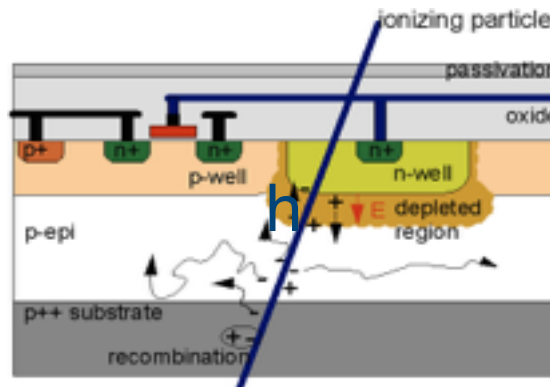


MONOLITHIC PIXEL SENSORS

- Some HEP applications (Linear Collider etc.) require extremely good spatial resolution (factor 2-5 better than at LHC) and very low material in the tracker
- Hybrid pixel sensors are too thick for such applications
- Investigating technologies with sensor and readout electronics in one layers -> monolithic
- Four different technologies:
 - CCD, DEPFET, CMOS, and 3D
 - different variants of each technology approach under investigation
- Some of them were chosen as baseline technology for real experiments
 - DEPFET for Belle II @KEK (Japan)
 - Mimoso MAPS for Star @ RHIC (USA)



DEPFET

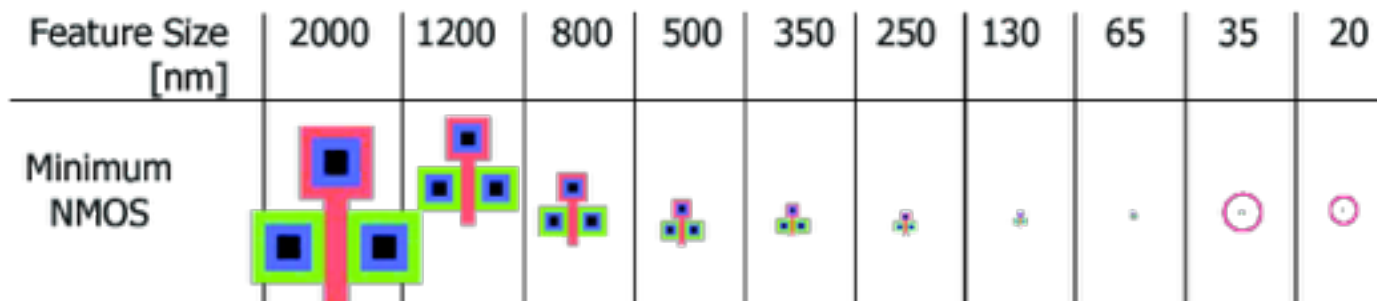
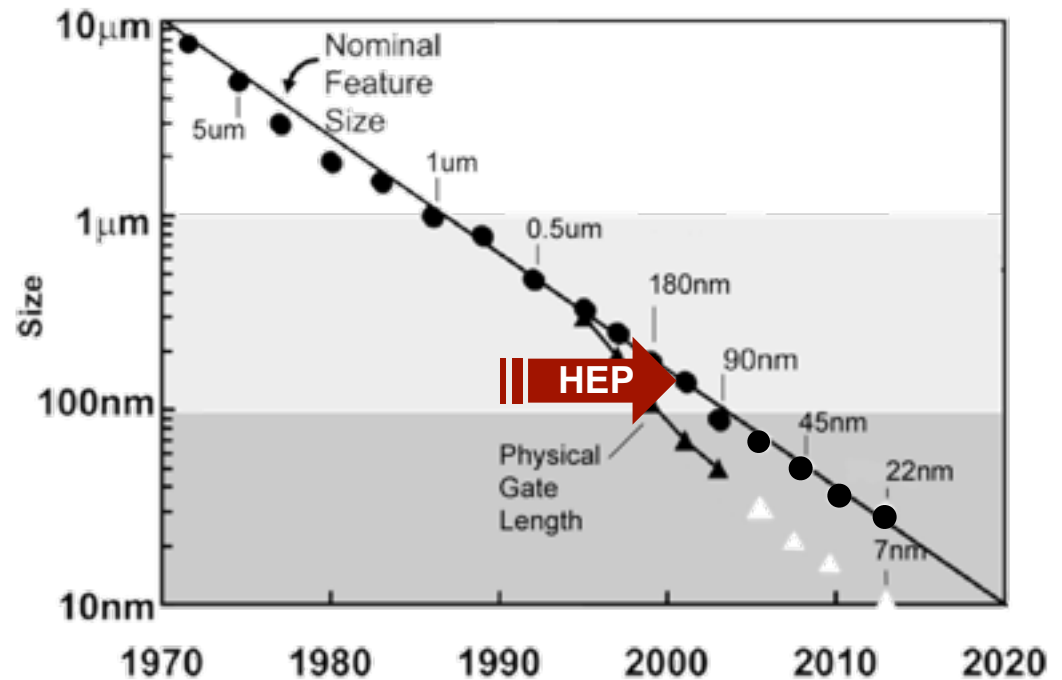


Mimosa MAPS

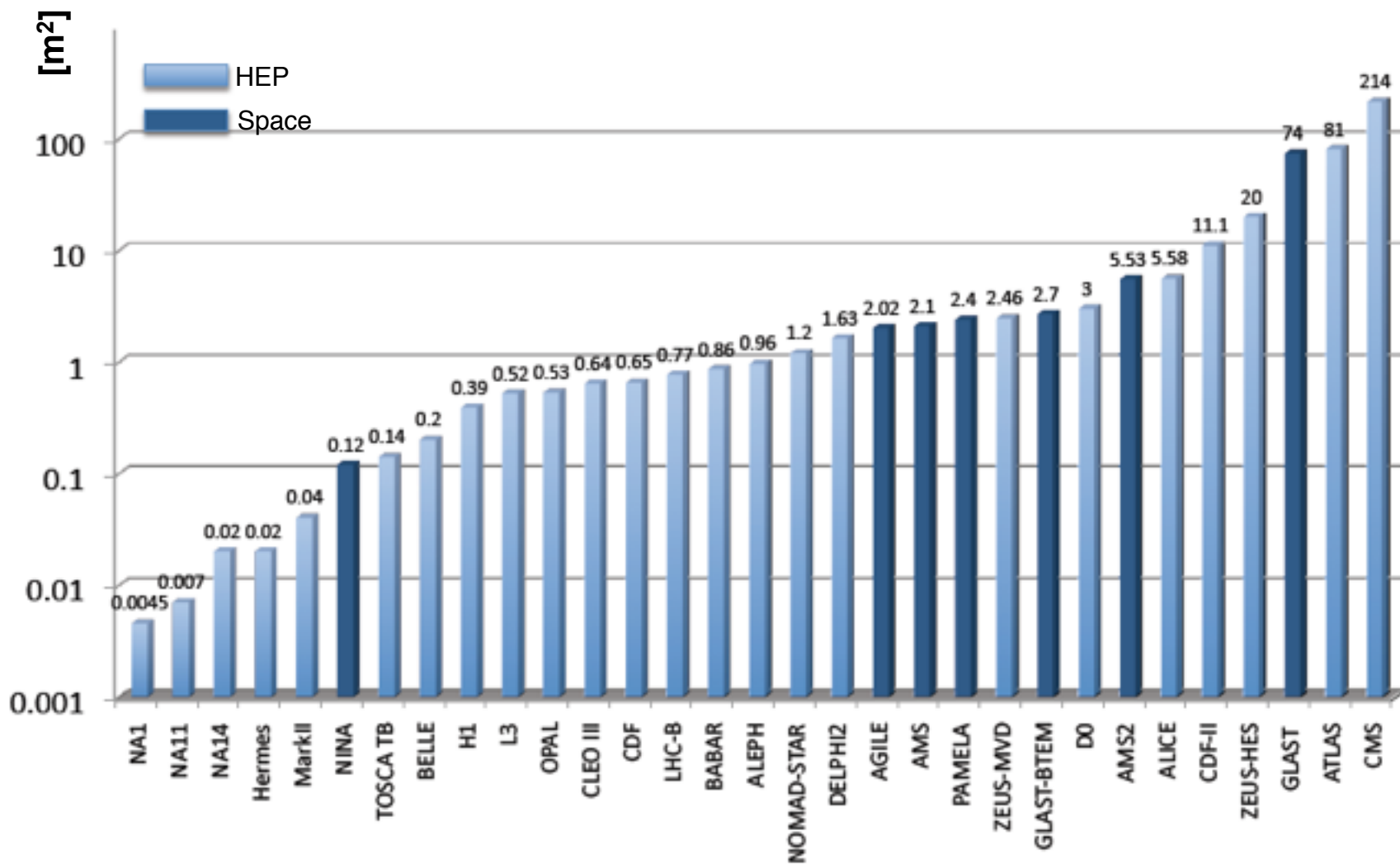
$< 20\mu\text{m}$

INDUSTRY SCALING ROADMAP

- New generation every ~ 2 years with $\alpha = \sqrt{2}$
- from 1970 (8 μm) to 2013 (22 nm) (industrial application)
- End of the road ? Power dissipation sets limits
- HEP nowadays at 90nm and 130nm
- Problem: by the time a technology is ready for HEP \rightarrow "old" in industry standards



SILICON DETECTOR SIZE 1981 - 2006



SUMMARY TRACKING DETECTORS

- Tracking detectors are playing an important role in HEP since the late 50ties
- Starting with bubble chamber the development of tracking detectors was rather rapidly
- Modern gas detectors and silicon trackers play an equal important role in HEP
- LHC silicon trackers are used for the inner systems while gas detector dominate the outer tracking systems (muon detectors)
- The technologies are rapidly evolving giving hope to have really fancy detectors for example for the future LC



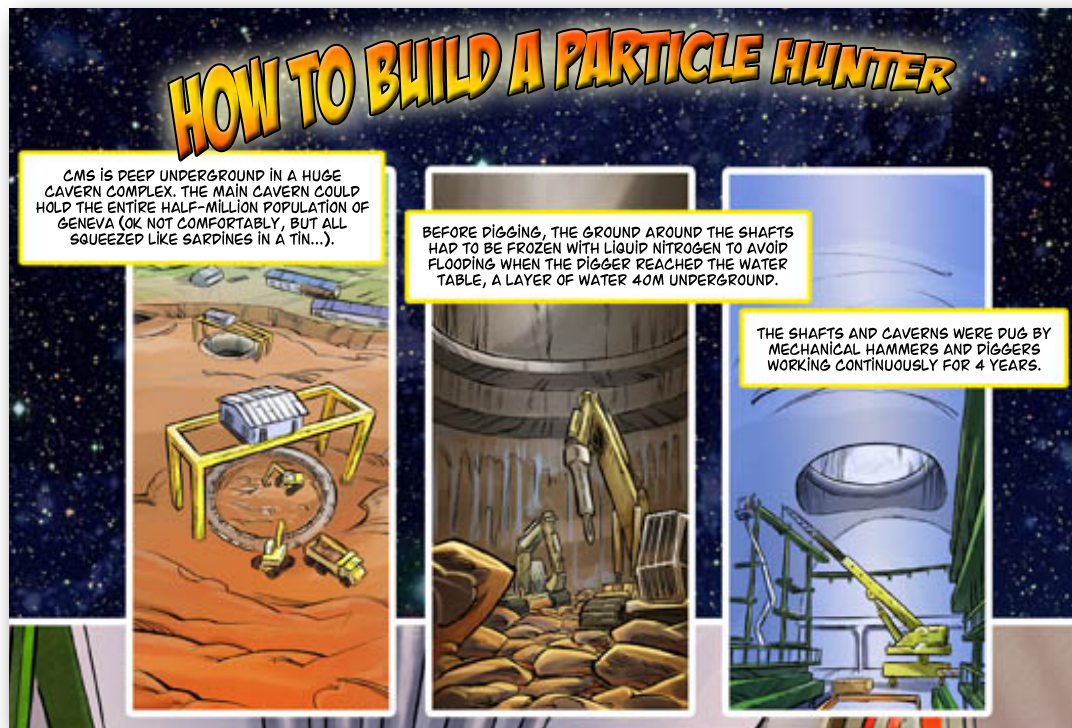
V. REAL LIFE EXAMPLES

BUILDING AN EXPERIMENT (AT LHC)

CURRENT HEP DETECTOR R&D

- Detector development is always an important topic in high energy physics
- Technical demands are constantly increasing due to new challenges in particle physics
 - higher occupancy, smaller feature size, larger trigger rates, radiation level,

- New HEP detector projects are planned for
 - Detector upgrades during different LHC phases up to HL-LHC (ATLAS, CMS, ALICE, LHCb)
 - Detector R&D for a future linear collider (ILC and CLIC)
 - Belle II (construction phase starting)
 - PANDA and CBM @Fair
 -



source: "CMS Particle Hunter"

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HOW TO DO A PARTICLE PHYSICS EXPERIMENT

- Recipe:
 - get particles (e.g. protons, antiprotons, electrons, ...)
 - accelerate them
 - collide them
 - observe and record the events
 - analyse and interpret the data

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- Ingredients needed:
 - particle source
 - accelerator and aiming device
 - detector
 - trigger
 - recording devices

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- many people to:

- design, build, test, operate accelerate
- design, build, test, calibrate, operate, understand the detector
- analyse data



Pic: DESY

typical HERA collaboration: ~400 people
LHC collaborations: >2000 people

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- analyse data
- lots of money to pay all this



Pic: DESY

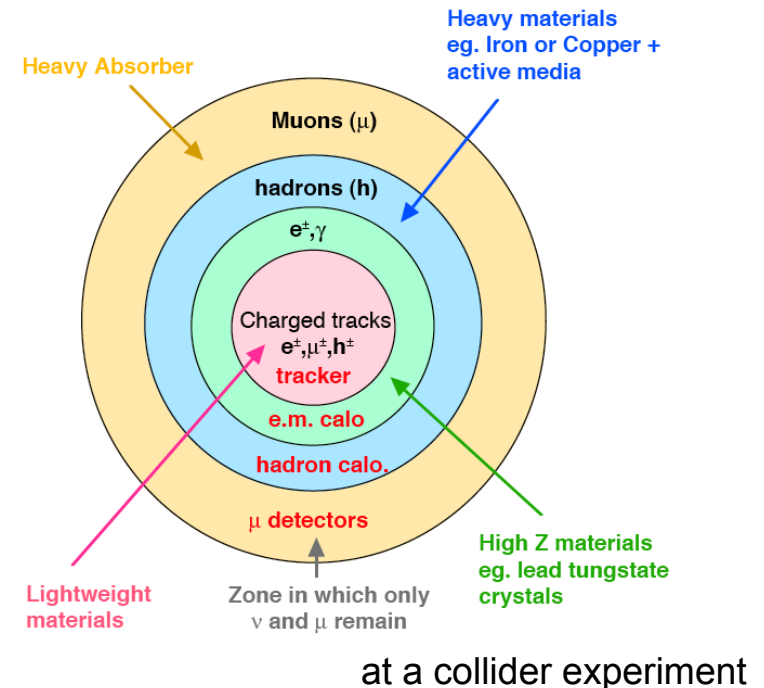
typical HERA collaboration: ~400 people
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CONCEPTUAL DESIGN OF HEP DETECTORS

- Need detailed understanding of
 - processes you want to measure (“physics case”)
 - signatures, particle energies and rates to be expected
 - background conditions
- Decide on magnetic field
 - only around tracker?
 - extending further ?
- Calorimeter choice
 - define geometry (nuclear reaction length, X_0)
 - type of calorimeter (can be mixed)
 - choice of material depends also on funds

- Tracker
 - technology choice (gas and/or Si?)
 - number of layers, coverage, ...
 - pitch, thickness,
 - also here money plays a role



Detailed Monte Carlo Simulations need to guide the design process all the time !!

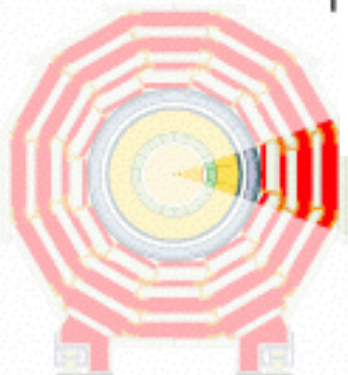
HEP DETECTOR OVERVIEW

Tracker: Precise measurement of track and momentum of charged particles due to magnetic field.

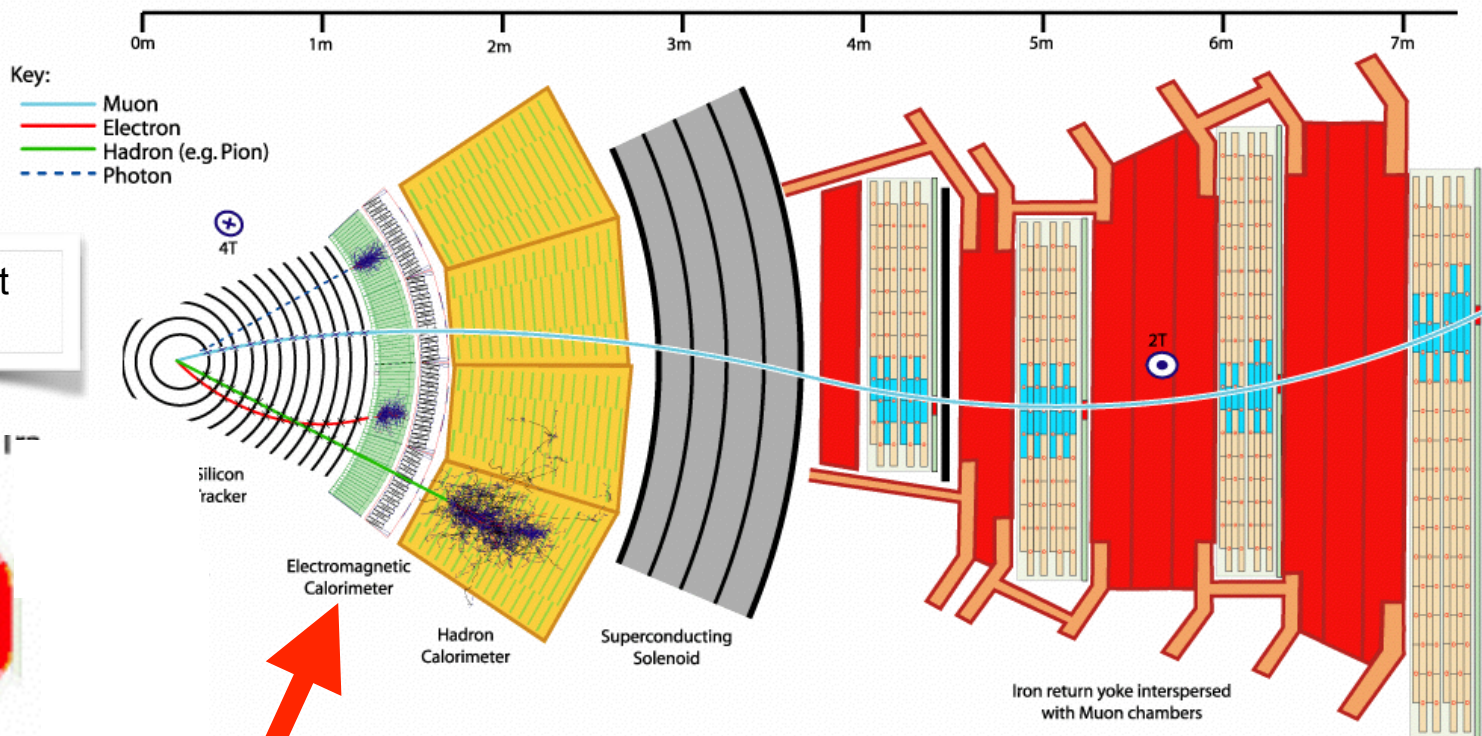
Calorimeter: Energy measurement of photons, electrons and hadrons through total absorption

Muon-Detectors: Identification and precise momentum measurement of muons outside of the magnet

Vertex: Innermost tracking detector



Transverse slice through CMS



Good energy resolution up to highest energies

picture: CMS@CERN

A MAGNET FOR A LHC EXPERIMENT

● **Wish list**

- big: long lever arm for tracking
- high magnetic field
- low material budget or outside detector (radiation length, absorption)
- serve as mechanical support
- reliable operation
- cheap
-



Eierlegende Wollmilchsau

● **ATLAS decision**

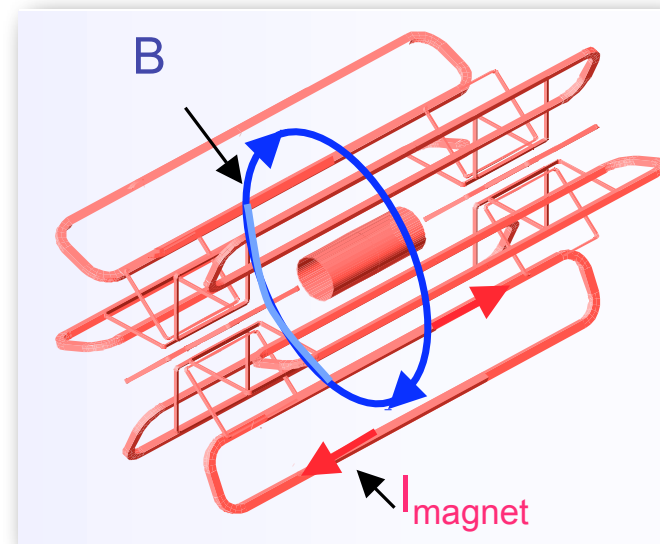
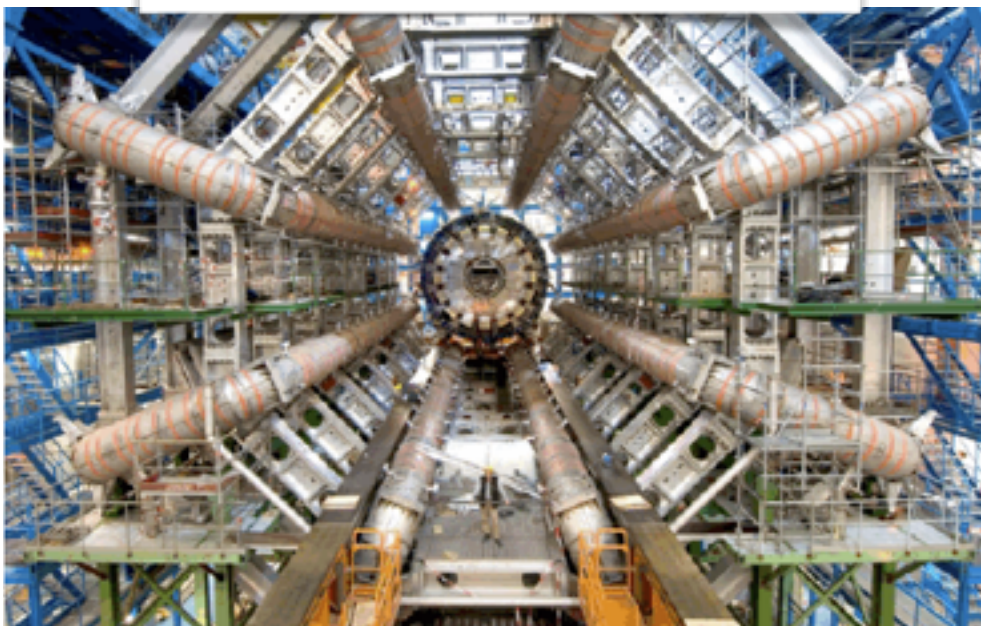
- achieve a high-precision stand-alone momentum measurement of muons
- need magnetic field in muon region -> large radius magnet

● **CMS decision**

- single magnet with the highest possible field in inner tracker (momentum resolution)
- muon detector outside of magnet

MAGNET-CONCEPTS: ATLAS -> TOROID

the largest magnet in the world

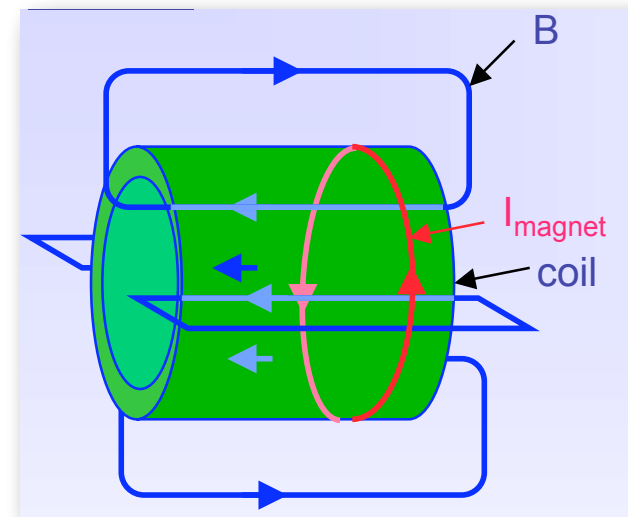


- Central toroid field outside the calorimeter within muon-system: <4 T
 - Closed field, no yoke
 - Complex field
- Thin-walled 2 T Solenoid-field for trackers integrated into the cryostat of the ECAL barrel

- + field always perpendicular to \underline{p}
- + relative large field over large volume
- non uniform field
- complex structure

MAGNET-CONCEPTS: CMS -> SOLENOID

Largest solenoid in the world:



- super conducting, 3.8 T field inside coil
- weaker opposite field in return yoke (2T)
- encloses trackers and calorimeter
- 13 m long, inner radius 5.9 m, $I = 20$ kA, weight of coil: 220 t

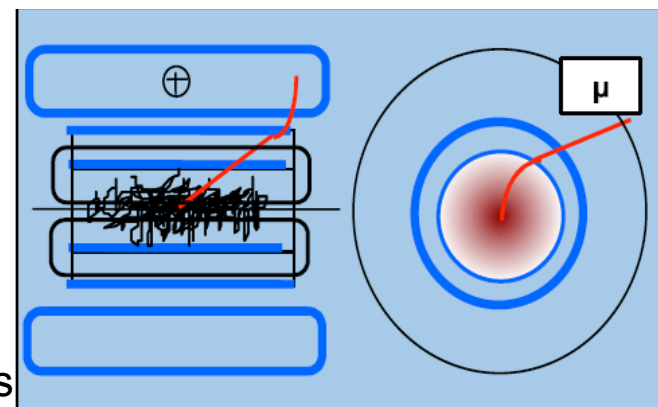
- + large homogeneous field inside coil
- + weak opposite field in return yoke
- size limited (cost)
- relative high material budget

MUON DETECTORS

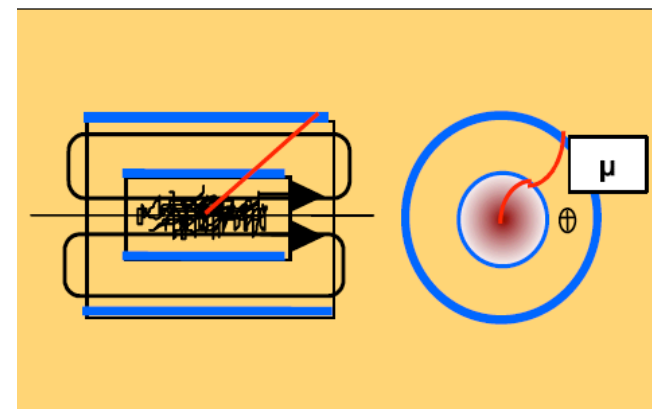
another tracker outside of the magnet

- Identification and precise momentum measurement of muons outside of the magnet
- Benchmark design for muon detectors: momentum measurement better than 10% up to 1 TeV.
 - $\Delta p_T/p_T \approx 1/BL^2$
- ATLAS
 - independent muon system -> excellent stand capabilities
- CMS:
 - superior combined momentum resolution in the central region;
 - limited stand-alone resolution and trigger capabilities (multiple scattering in the iron)
- ATLAS and CMS have both a combination of different gas detectors in the larger radius
 - Drift tubes
 - Resistive plate chambers
 - Multi-wire proportional chamber

ATLAS



CMS



OVERVIEW OF CALORIMETERS

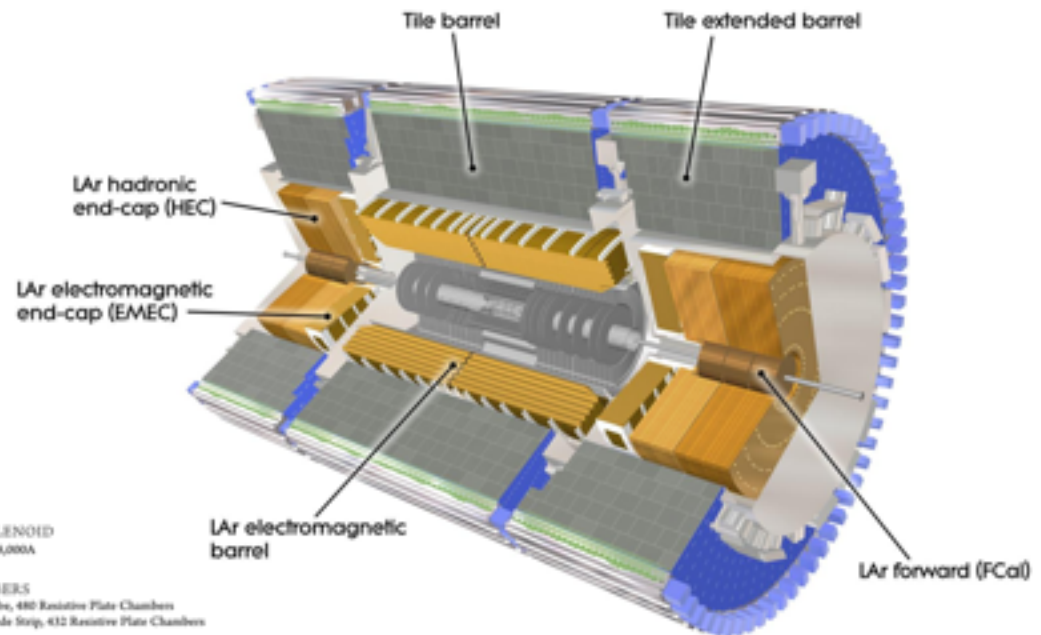
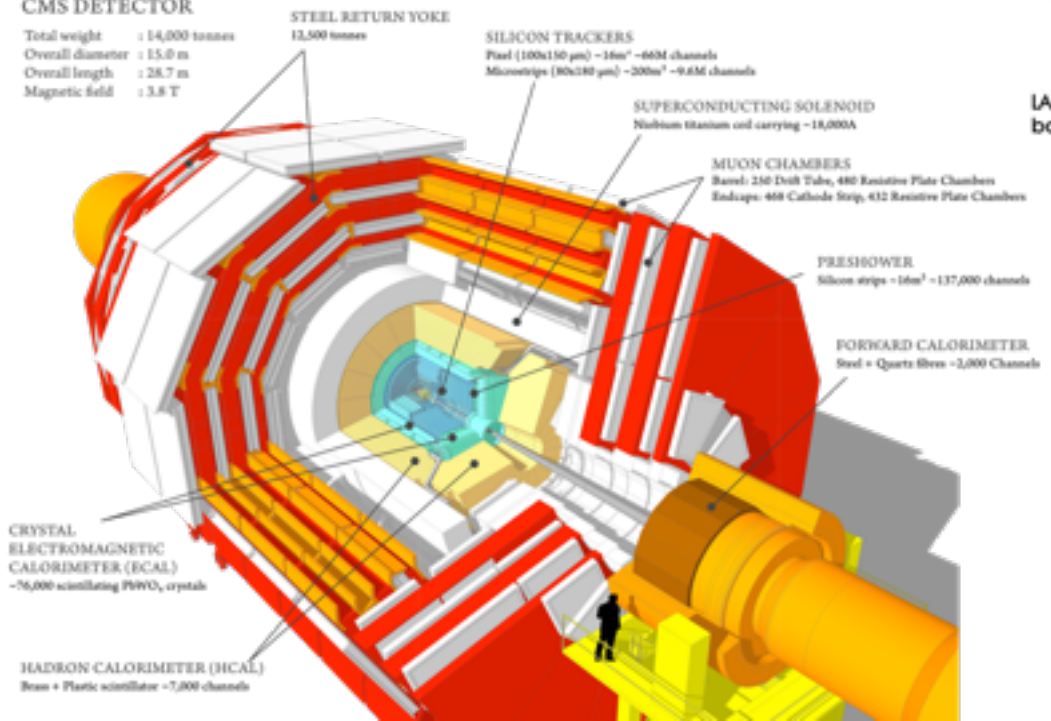
ATLAS

- In order to maximize the sensitivity for $H \rightarrow \gamma\gamma$ decays, the experiments need to have an excellent $e\gamma$ identification and resolution

CMS

CMS DETECTOR

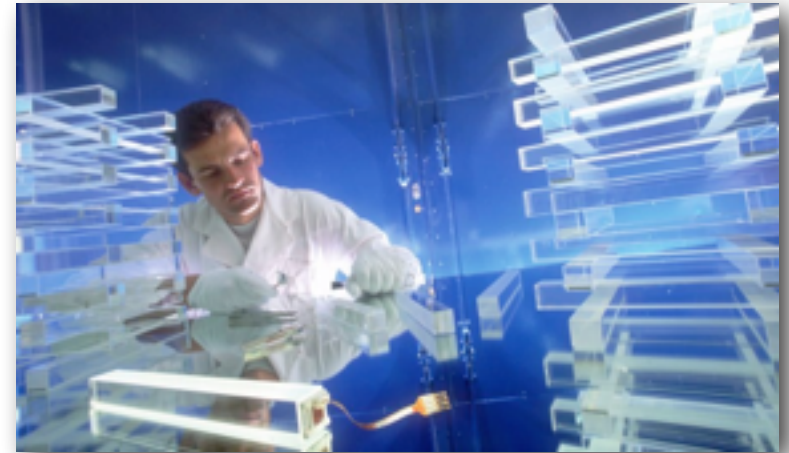
Total weight : 14,000 tonnes
 Overall diameter : 15.8 m
 Overall length : 28.7 m
 Magnetic field : 3.8 T



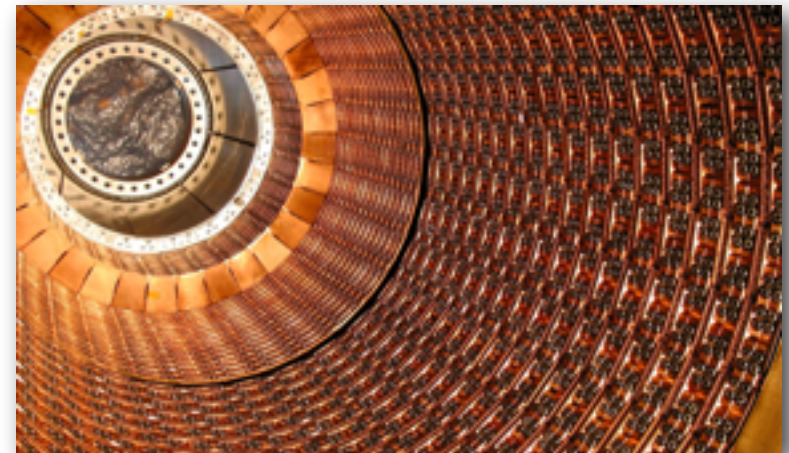
IMPORTANT DIFFERENCES: CALORIMETER

- **CMS:** homogeneous calo
 - high resolution Lead Tungsten crystal calorimeter -> **higher intrinsic resolution**
 - constraints of magnet -> HCAL absorption length not sufficient
 - tail catcher added outside of yoke

- **ATLAS:** sampling calo (ECAL + HCAL)
 - liquid argon calorimeter -> high granularity and longitudinally segmentation (better e/ ID)
 - electrical signals, high stability in calibration & radiation resistant (gas can be replaced)
 - solenoid in front of ECAL -> a lot of material reducing energy resolution
 - accordion structure chosen to ensure azimuthal uniformity (no cracks)
 - liquid argon chosen for radiation hardness and speed



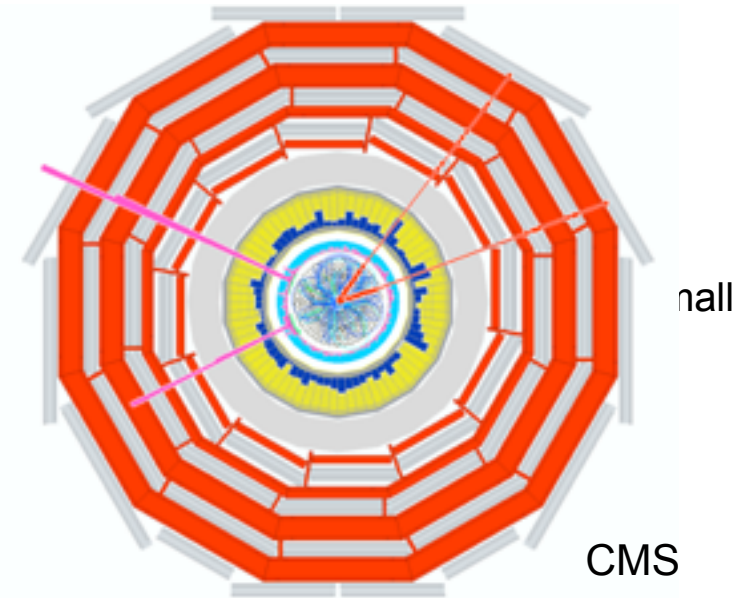
CMS Lead tungsten crystals (CERN)



ATLAS Hadronic endcap Liquid Argon Calorimeter. (CERN)

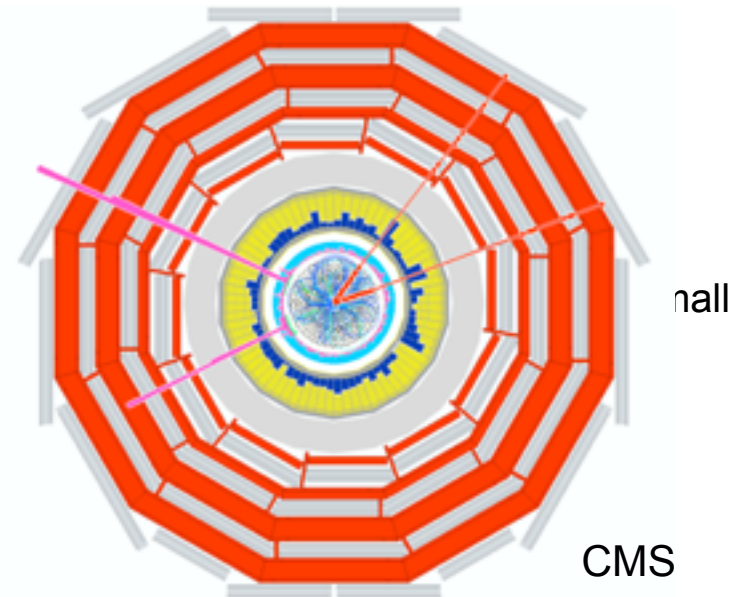
WHAT IS A TRIGGER ?

- Collisions every 25 ns with many simultaneous interactions
- A lot of information stored in the detectors - we need all information
- Electronics too slow to read out all information for **every** collision
- But: a lot of the interactions are very well known - we only want a few
- “Trigger” is a system that uses simple criteria to rapidly decide which fraction of the total can be recorded.



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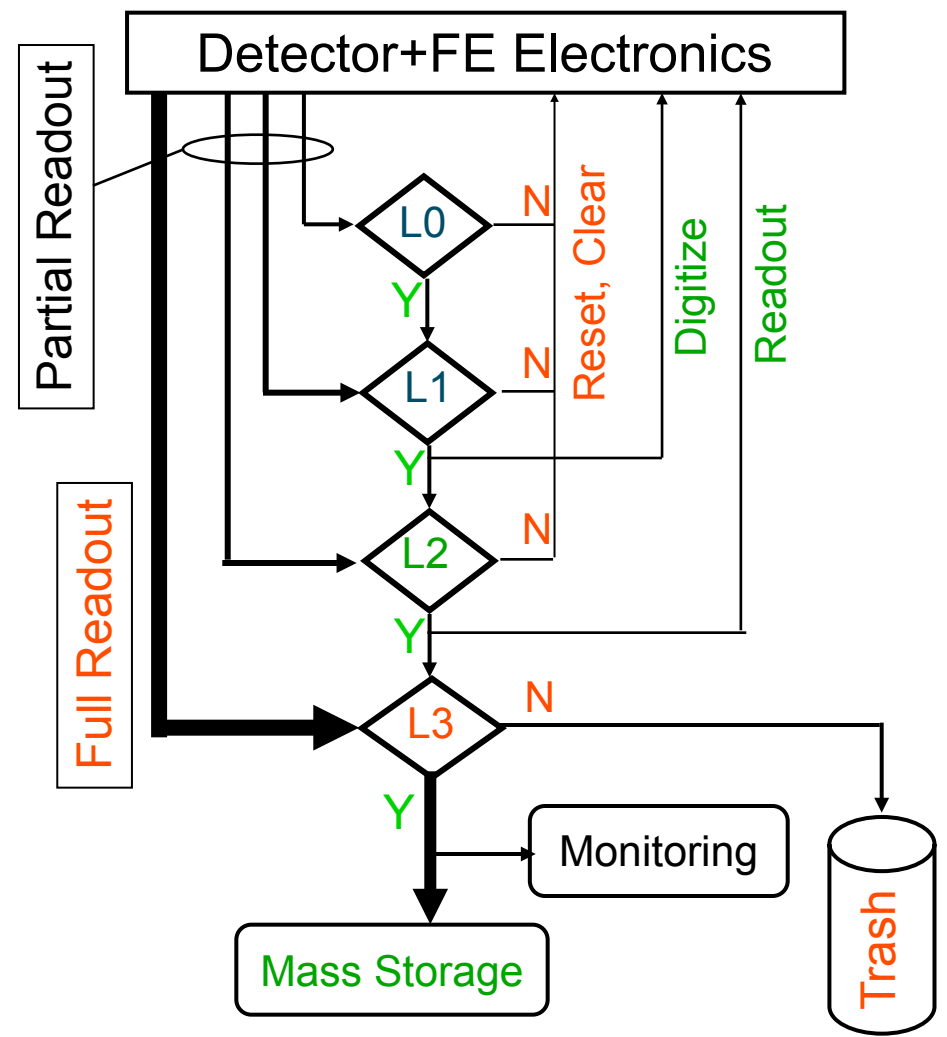
- Want to know the information of green cars
 - number of passengers
 - speed
 - weight
 -
- Trigger = system detecting the color and initiating the information transfer of all information



MULTI-LEVEL TRIGGER SYSTEMS

High Efficiency ↔ **Large Rejection**

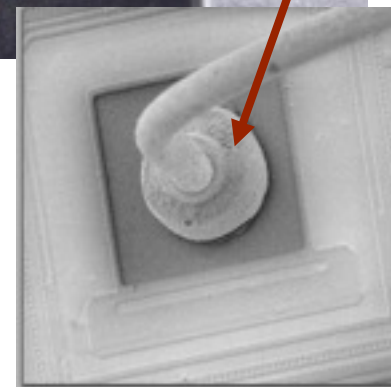
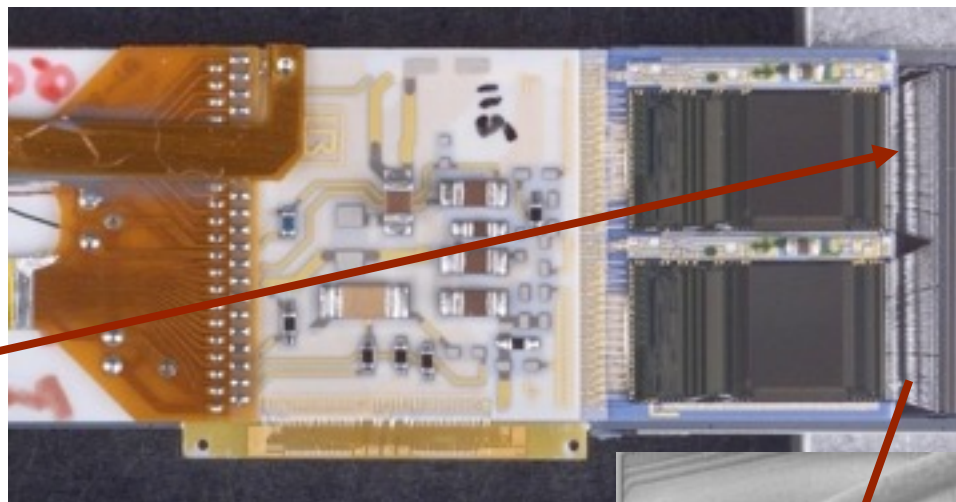
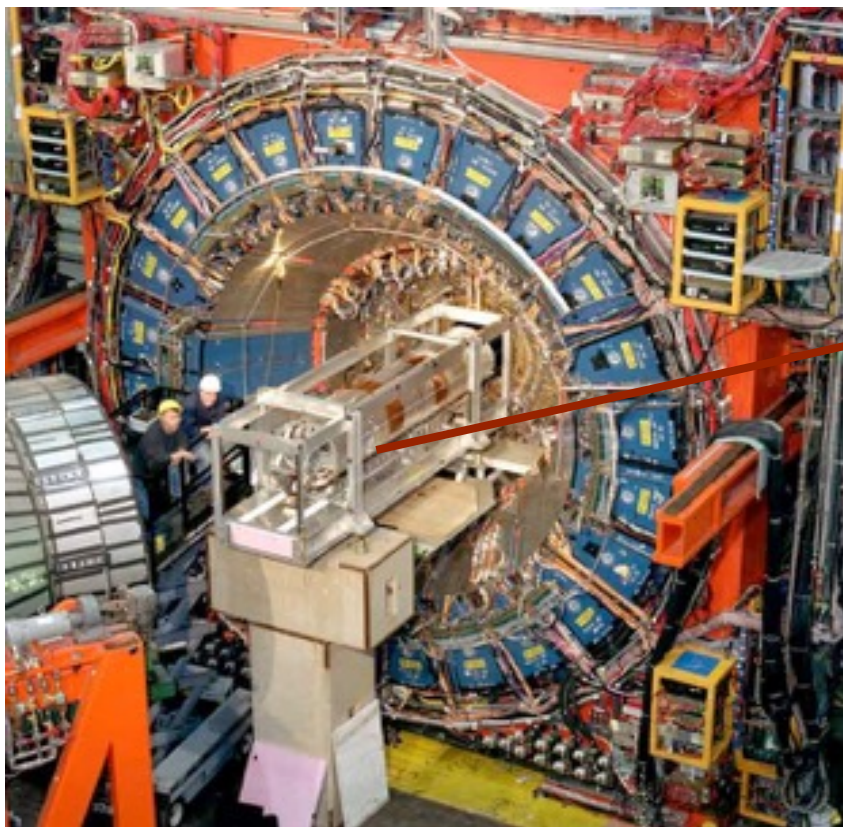
- Can't achieve necessary rejection in a single triggering stage
- Reject in steps with successively more complete information
 - L0 – very fast (<~bunch x-ing), very simple, usually scint. (TOF or Lumi. Counters)
 - L1 – fast (~few μ s) with limited information, hardware
 - L2 – moderately fast (~10s of μ s), hardware and sometimes software
 - L3 – Commercial processor(s)
- Next generation: implement triggering stage already in tracking detector to handle very high multiplicities (example: HL-LHC)
- Other extreme: trigger-less operation -> read out at 40MHz and do the work offline (LHCb)



V. REAL LIFE EXAMPLES AND WHAT CAN GO WRONG ...

PROBLEMS WITH WIRE BONDS (CDF, DO)

- Very important connection technology for tracking detectors: wire bonds:
 - 17-20 μm small wire connection \rightarrow terrible sensitive
 - During test pulse operation, Lorentz force on bonding wires (perpendicular to magnetic field)
 - ...



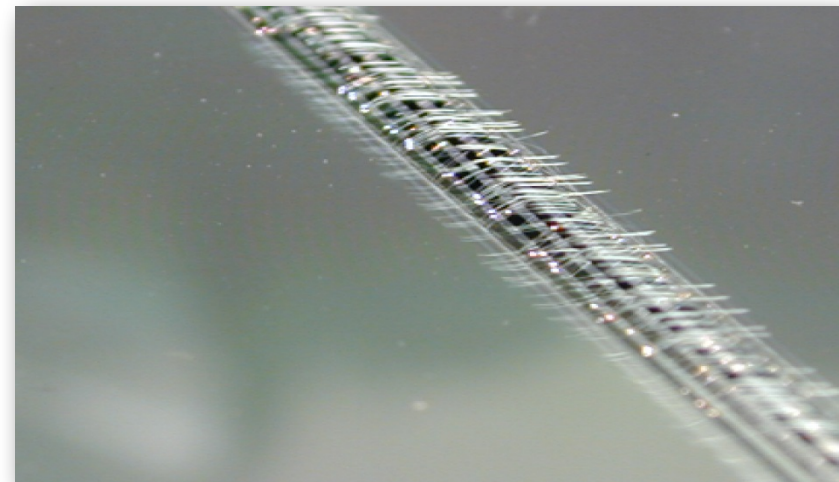
...breaks wire bonds between detector and read out.

during running

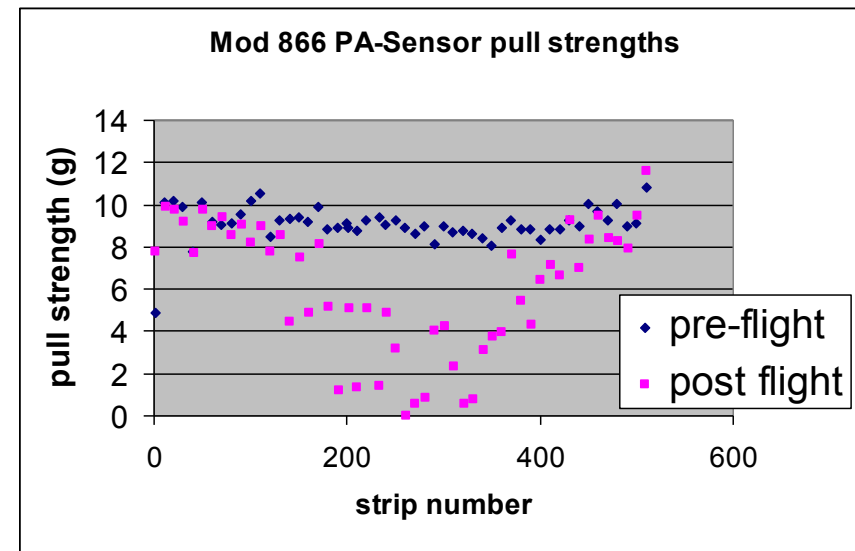
MORE WIRE BOND WRECKAGE

- Quality of wires is tested by pull tests (measured in g)
- During CMS strip tracker production quality assurance applied before and after transport (via plane)
- Wire bonds were weaker after flight
- Random 3.4 g NASA random vibration test causes similar damage

- Problem observed during production -> improved by adding a glue layer
- No further problems during production

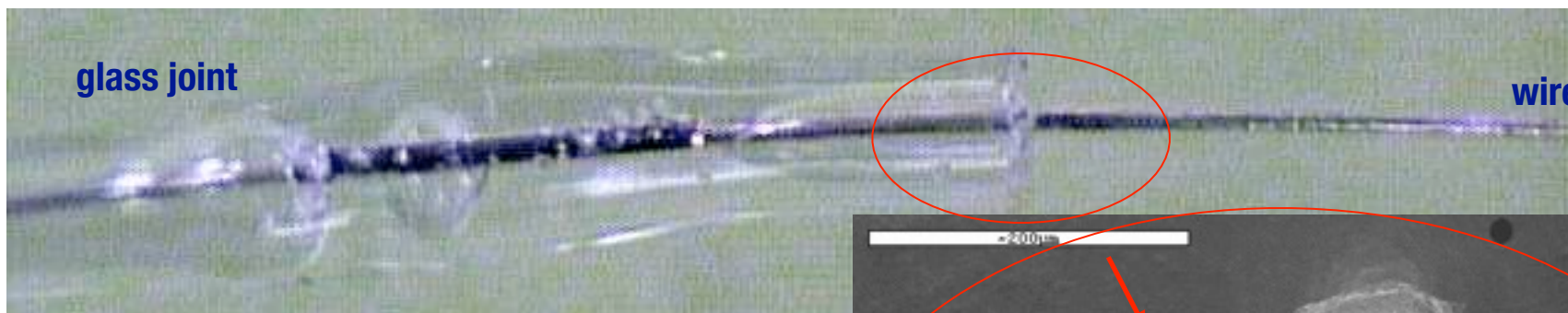


during production



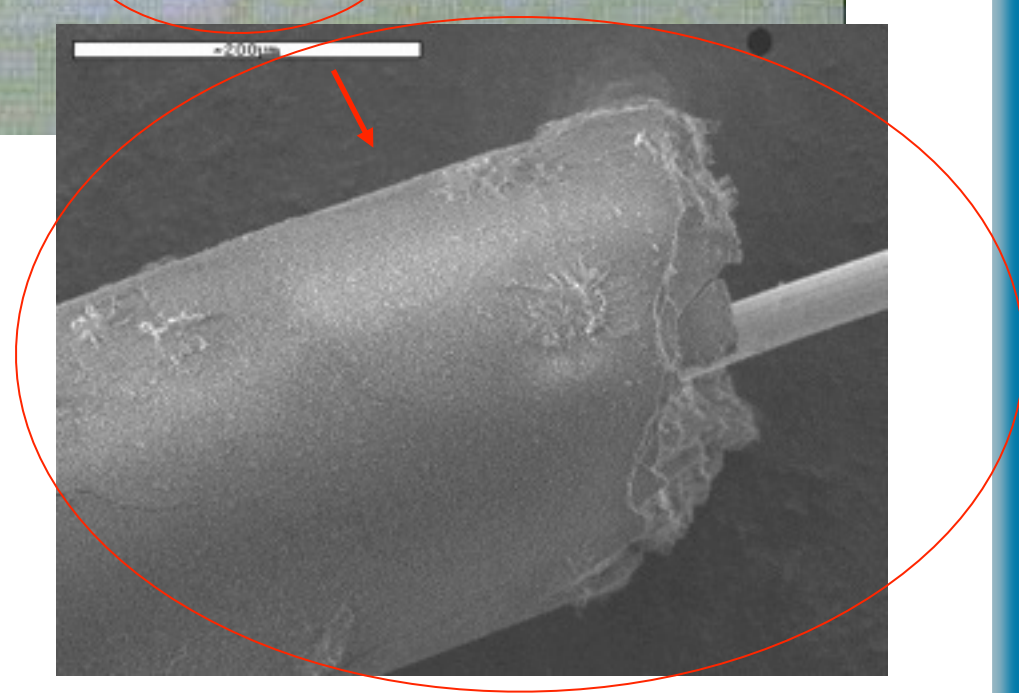
UNEXPECTED PROBLEMS ATLAS BARREL TRT

- Gas mixture: 70% Xe + 20 CF₄ + 10% CO₂
- Observed: **destruction of glass joint between long wires** after 0.3 - 0.4 integrated charge (very soon after start up)



At high irradiation C₄F turns partially into HF, F₂ (hydrofluoric acid)
 -> attaches Si-based materials in the detector

- Changed gas mixture,
 - after ~10 years of R&D with old mixture

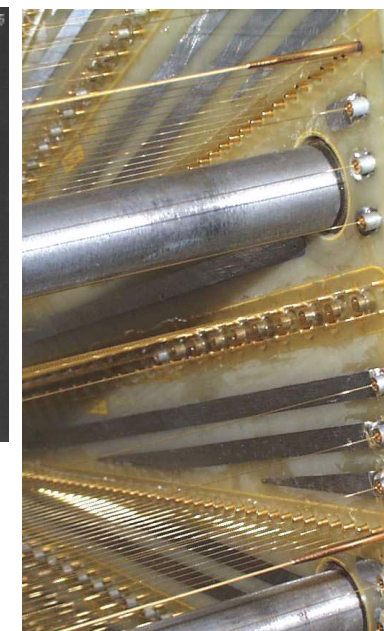
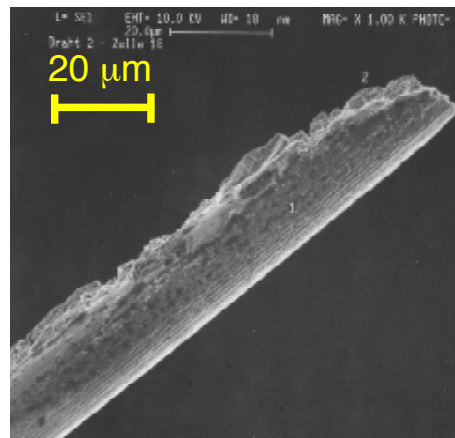


during production

WIRES H1 CENTRAL JET CHAMBER

during running

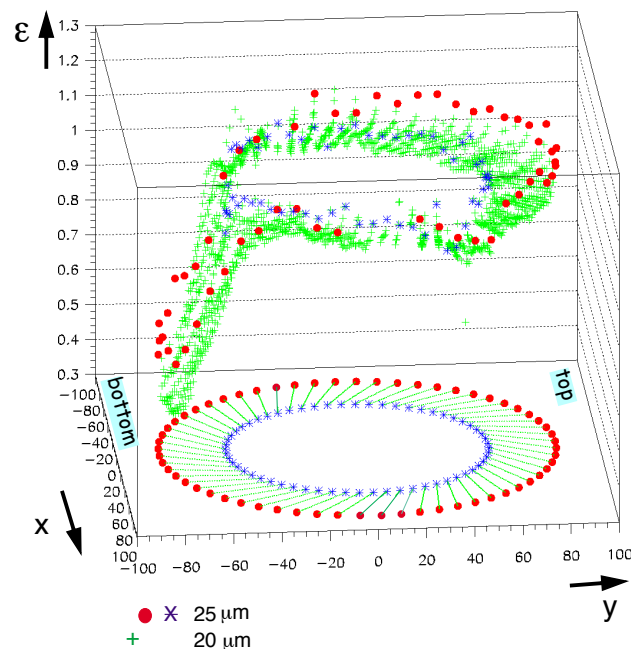
- Outer tracker of H1 ->
- Broken Wires in CJC1
- Observation / possible reason:
 - remnants from gold plating process lead to complex chemical reactions
- new design of crimp tube: jewels • better quality control



Cathode

Sense/Pot

Cathode

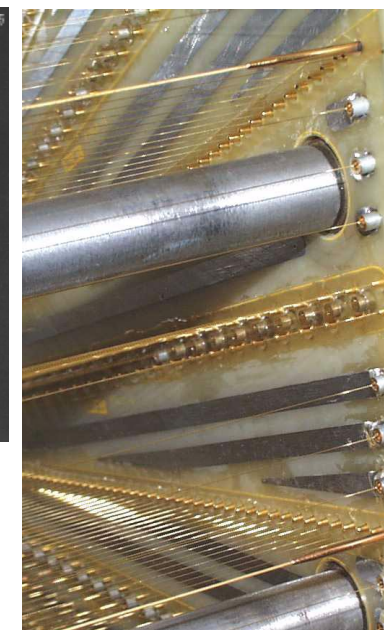
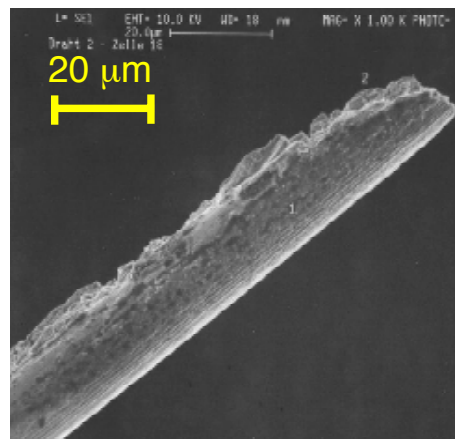


- Sense Wire Deposits in CJC2
- Observation / possible reason:
 - y dependence implies most likely gas impurity
- Consequences:
 - sense wires replaced
 - changes in gas distribution
 - increased gas flow

WIRES H1 CENTRAL JET CHAMBER

during running

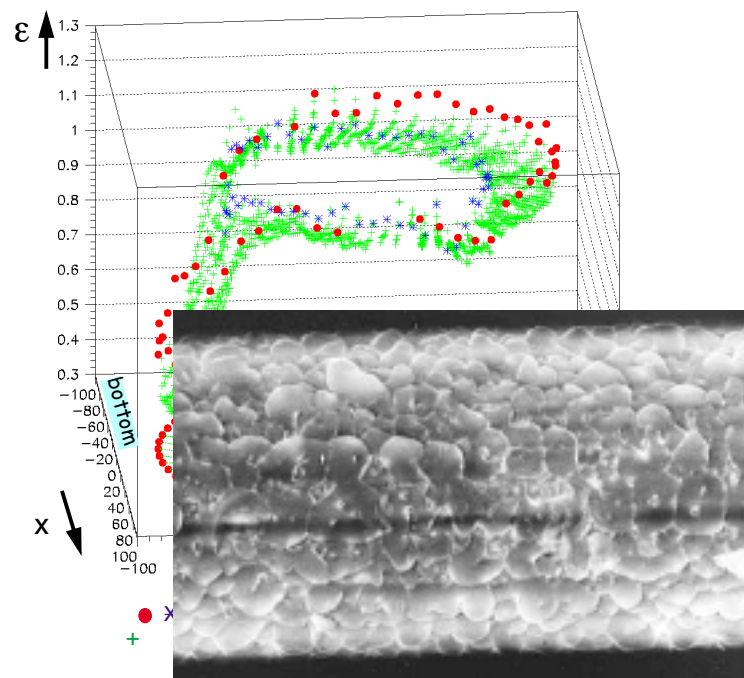
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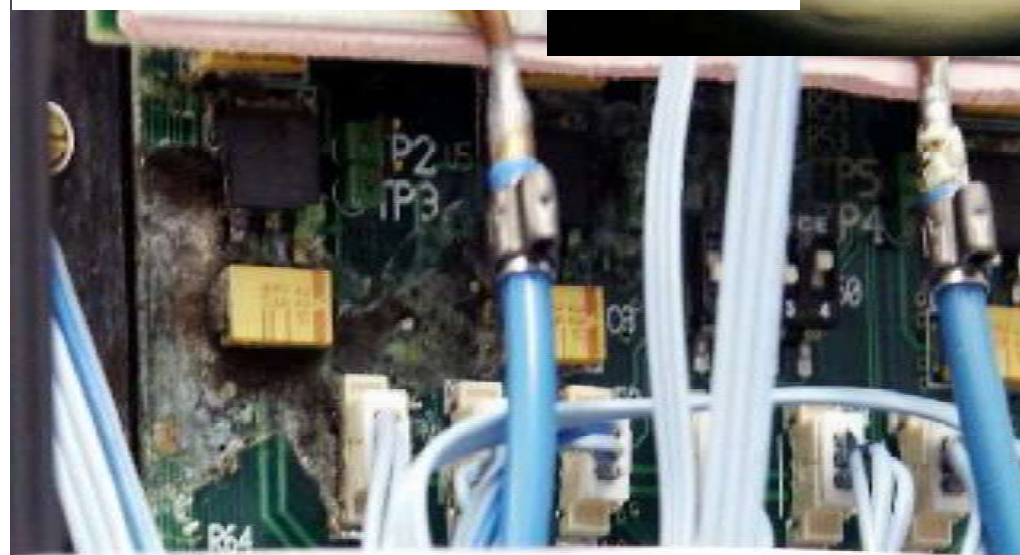
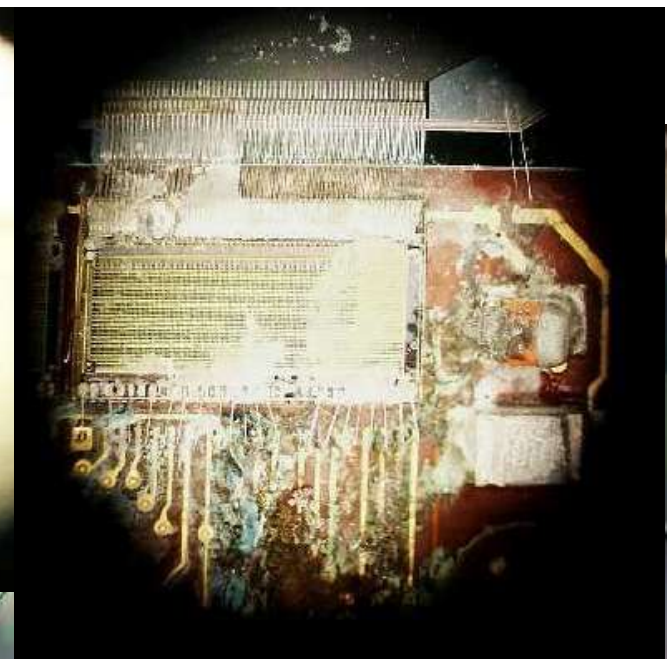


- Sense Wire Deposits in CJC2
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 - y dependence implies most likely gas impurity
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 - sense wires replaced
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 - increased gas flow

WATER DAMAGE IN TRACKER ...

during running

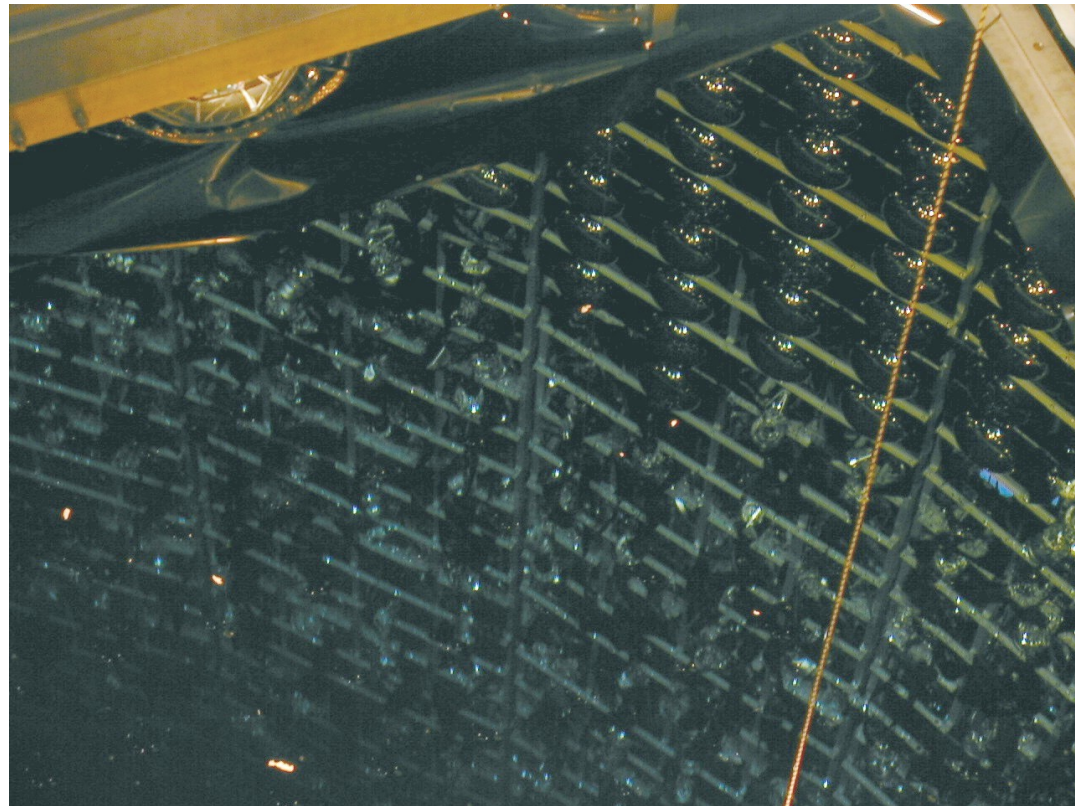
- H1@HERA FST in 2004
- Imperfect crimp + hardening of plastic => water leak
- Water condensation => damage
- Tracker segment had to be rebuilt



IMPLODED PMTs @ SUPERKAMIOKANDE

- On November 2001 a PMT imploded creating a shock wave destroying about 6600 of other PMTs (costing about \$3000 each)
- Apparently in a **chain reaction** or **cascade failure**, as the **shock wave** from the concussion of each imploding tube cracked its neighbours.
- Detector was partially restored by redistributing the photomultiplier tubes which did not implode.

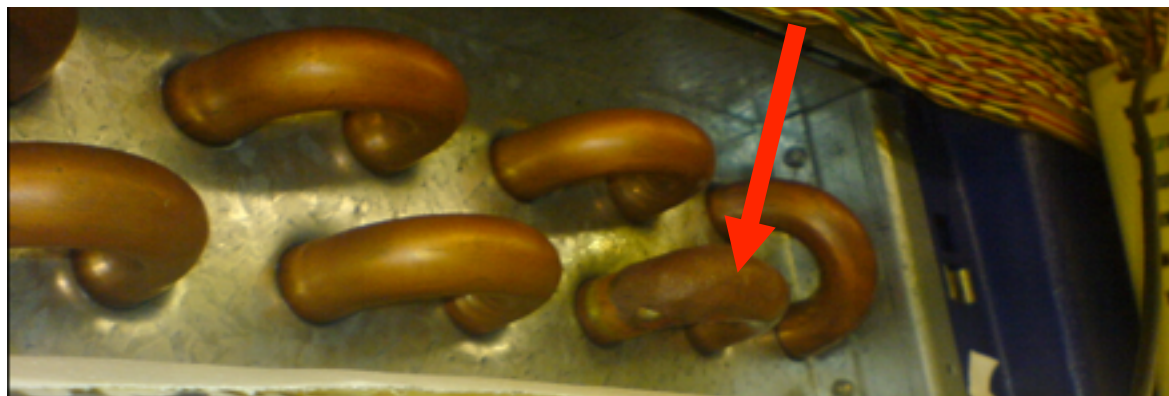
during running



Pic: unknown source....

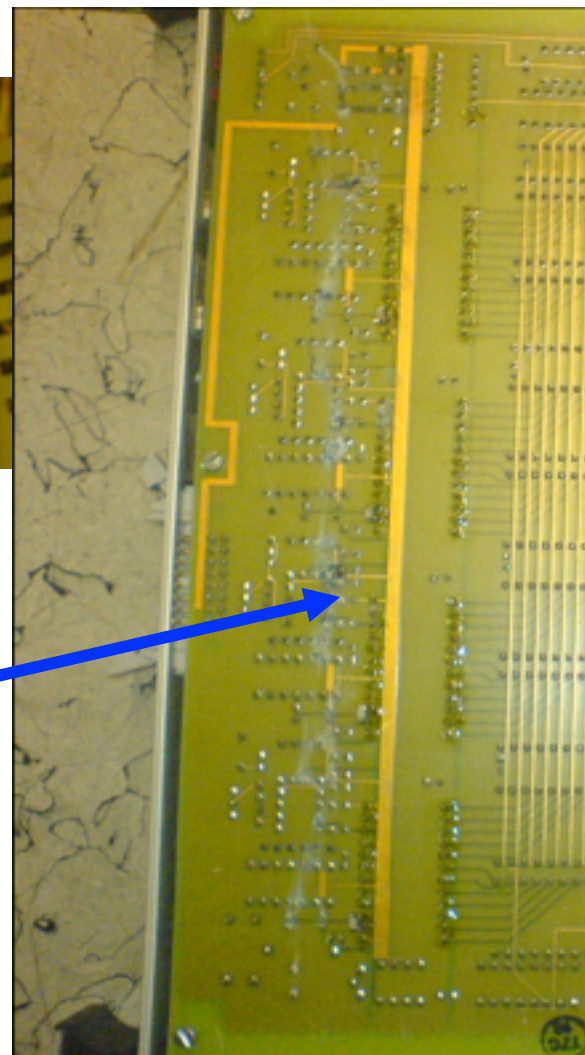
ZEUS - ONE OF MANY WATER LEAKS

- Where ever you chose to cool with a liquid - it will leak one day !



- Micro hole in copper hose led to water in the digital card crates
- Four crates were affected, but only seven cards were really showing traces of water
- Of course this all happened on a Saturday morning at 7am

during running



SUMMARY

- I could only give a **glimpse** at the wealth of particle detectors. More detectors are around: medical application, synchrotron radiation experiments, astro particle physics, ...
- All detectors base on similar principles
 - Particle detection is indirectly by (electromagnetic) interactions with the detector material
- Large detectors are typically build up in layers (onion concept):
 - Inner tracking: momentum measurement using a B-field
 - Outside calorimeter: energy measurement by total absorption
- Many different technologies:
 - Gas- and semiconductors (light material) for tracking
 - Sampling and Homogeneous calorimeters for energy measurement
- Similar methods are used in astro particle physics
- **Always looking for new ideas and technologies!**



LITERATURE

Text books:

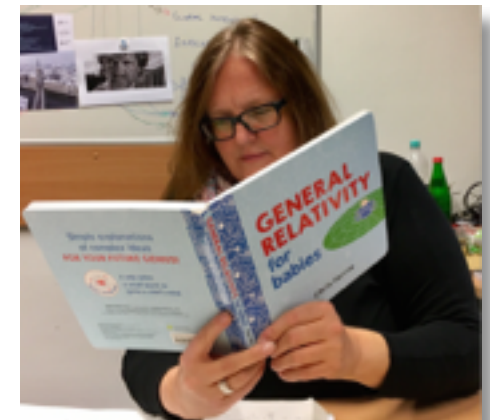
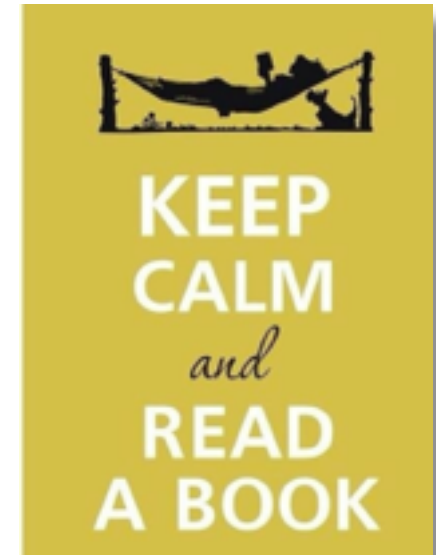
- N. Wermes, H. Kolanoski: Teilchendetektoren, Grundlagen und Anwendungen, Februar 2016, Springer
- Frank Hartmann, Evolution of Silicon Sensor Technology in Particle Physics, Springer Verlag 2017
- C.Grupen: Particle Detectors, Cambridge UP 22008, 680p
- D.Green: The physics of particle Detectors, Cambridge UP 2000
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- W.R. Leo: Techniques for Nuclear and Particle Physics Experiments, Springer 1994
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- Helmuth Spieler, Semiconductor Detector Systems, Oxford University Press 2005
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- F. Sauli, Principles of Operation of Multiwire Proportional and Drift Chambers
- G.Lutz: Semiconductor radiation detectors, Springer, 1999
- R. Wigmans: Calorimetry, Oxford Science Publications, 2000

web:

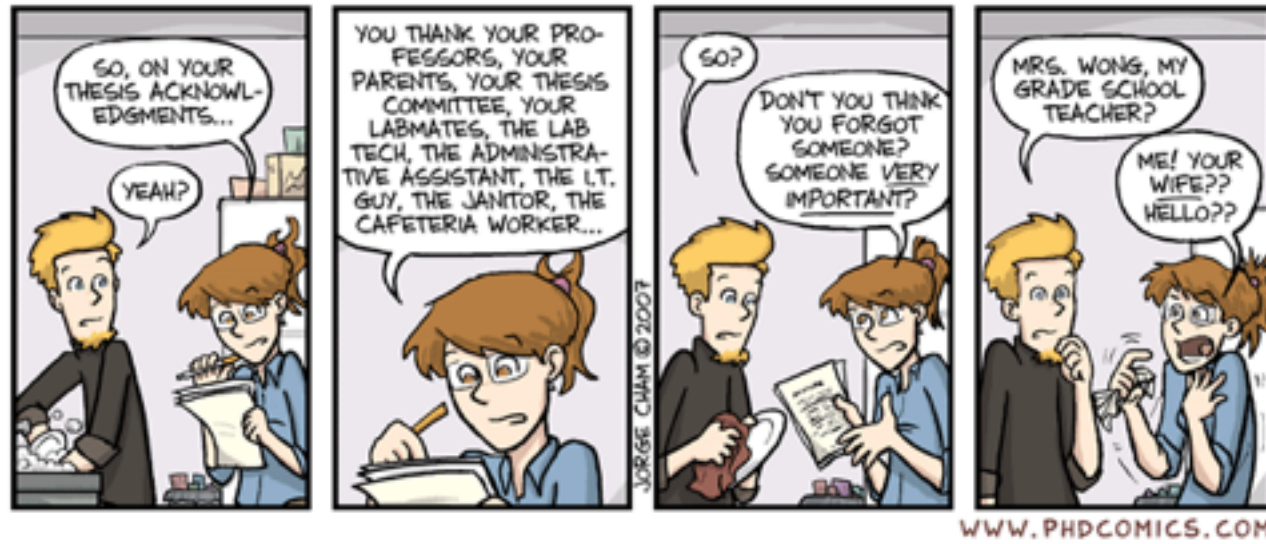
Particle Data Group: *Review of Particle Properties: pdg.lbl.gov*

further reading:

The Large Hadron Collider - The Harvest of Run 1; Springer 2015



IMPORTANT



Thanks to:

Frank Simon

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Marc Winter

Christoph Rembser

Doris Eckstein

Christian Joram

Steinar Stapnes

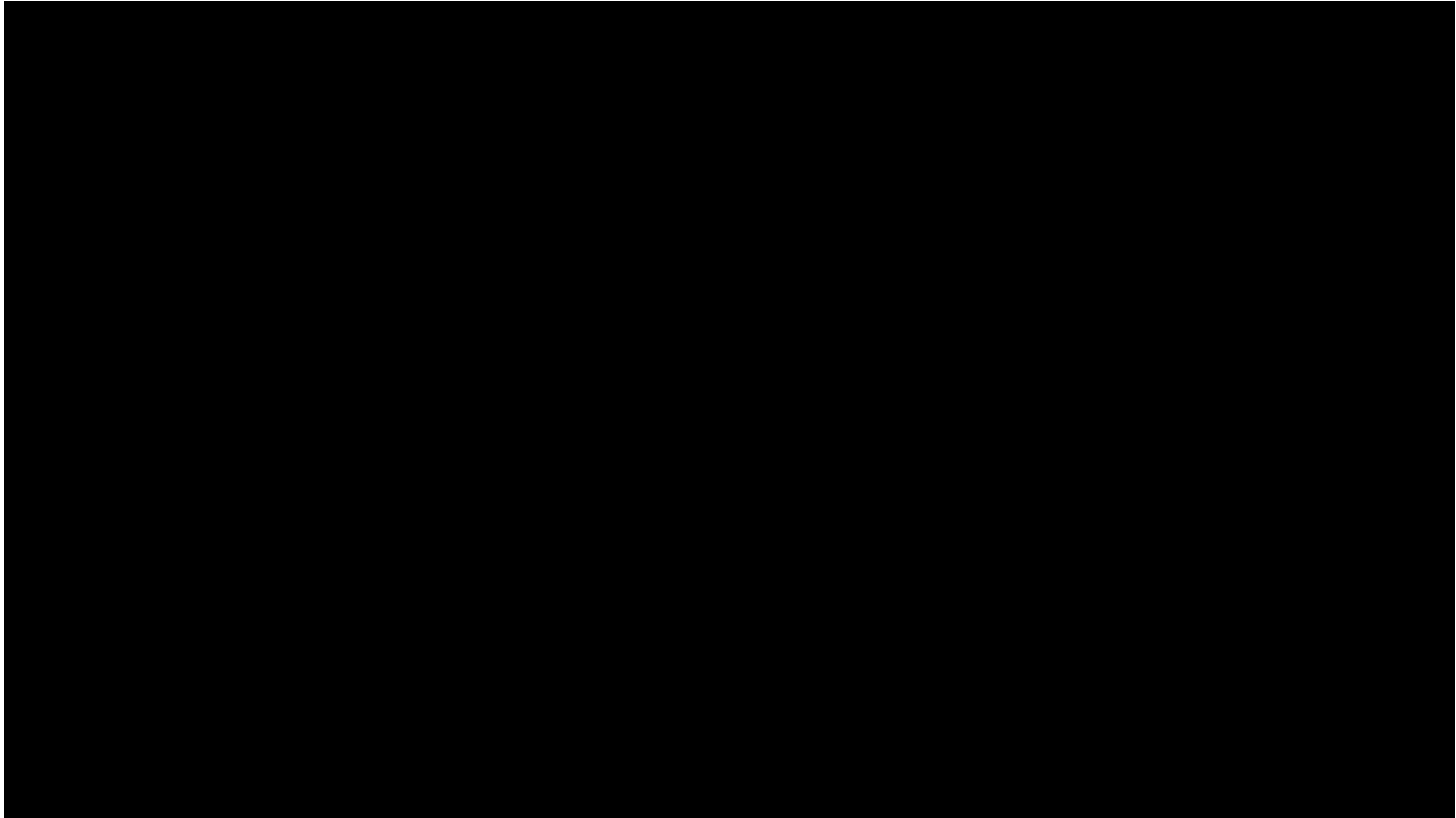
...freaky husband ;-)

SYMPHONY OF SCIENCE

Symphony of Science Video
<http://www.youtube.com/watch?v=DZGINaRUEkU>

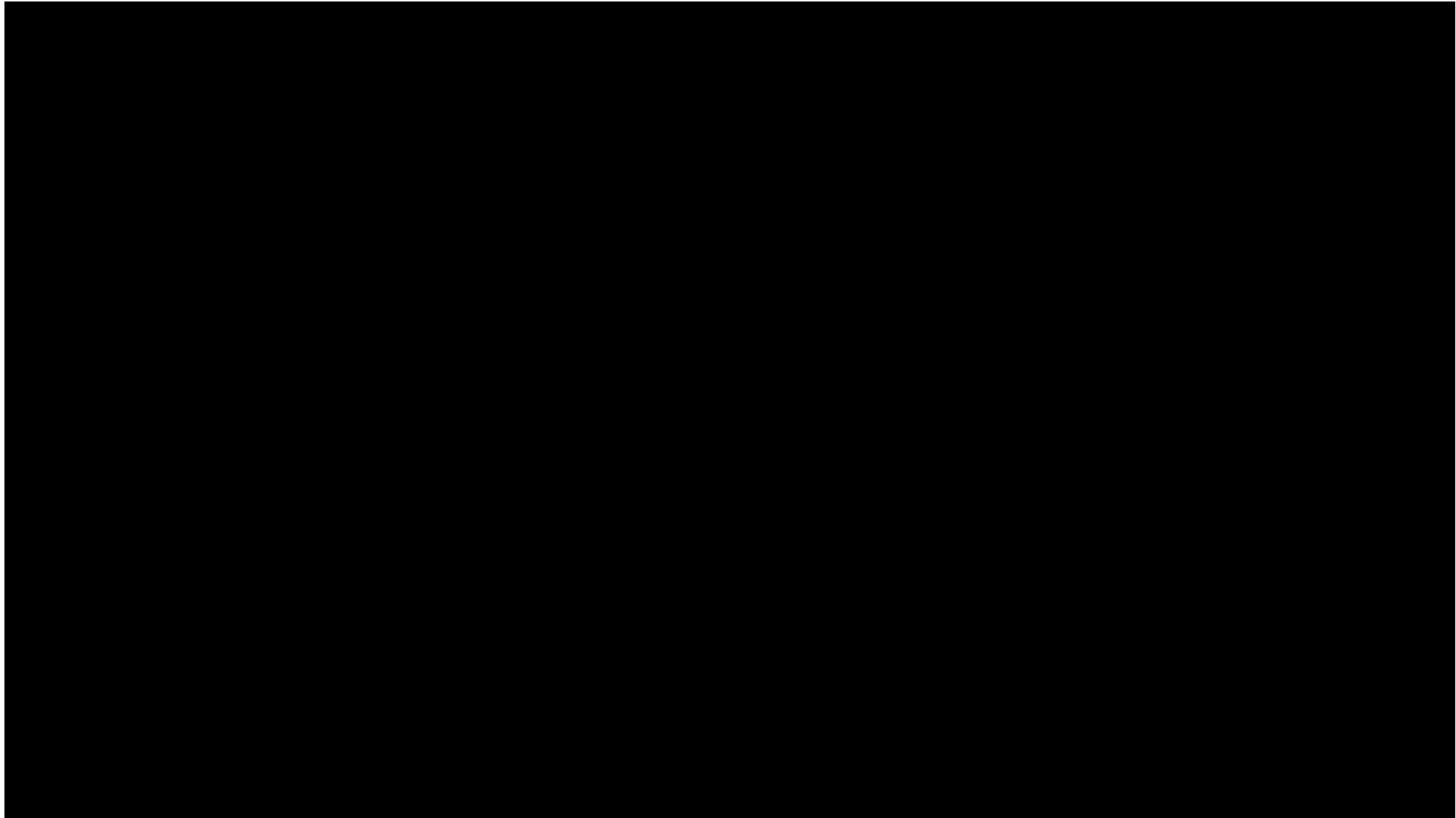


SYMPHONY OF SCIENCE



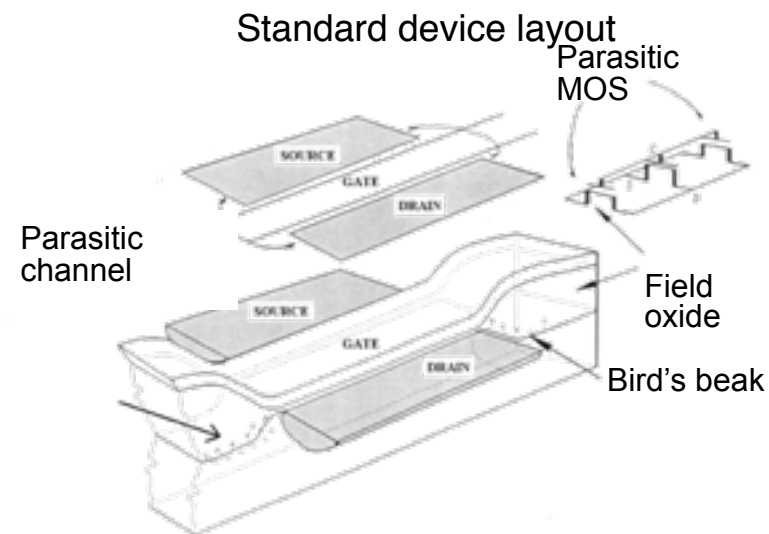


SYMPHONY OF SCIENCE

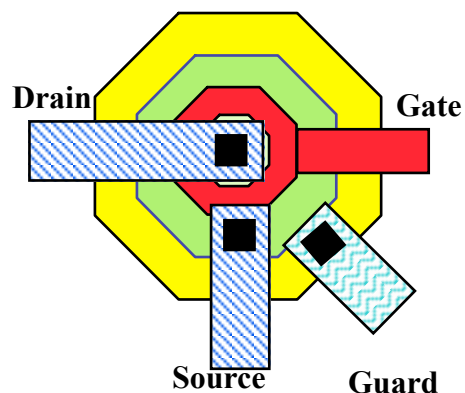


RADIATION EFFECTS ON CMOS: IONIZING

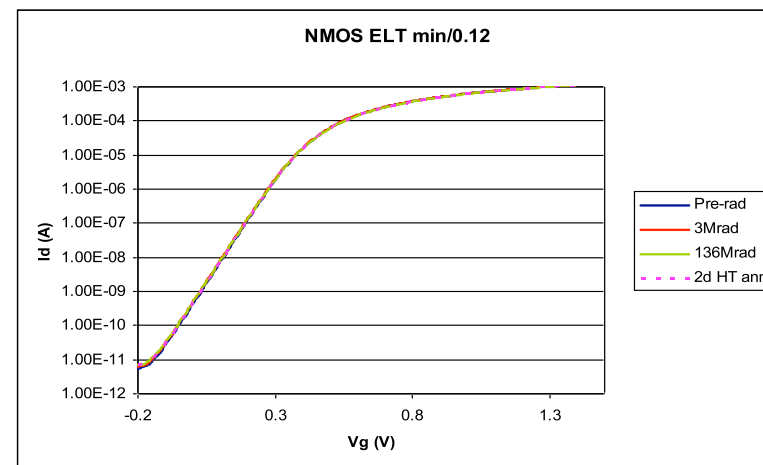
- Decrease of feature size: higher radiation tolerance:
 - Positive charge trapped in gate and field oxides
 - Trapped charge dissipates by tunnelling in thin-oxide transistors
- Radiation tolerant layout techniques designed by CERN RD49 in 0.25 μm to avoid parasitic transistor leakage
- New RD created for further work towards HL-HLC



Enclosed layout



gate encloses all n+ regions avoiding any thick transistor relevant oxide structures



TID on IBM 130nm NMOS [F. Faccio CERN]